MP2664

500mA, 5V USB, I²C-Controlled Battery Charger with Power Path Management for Single-Cell Li-Ion Battery in QFN Package

DESCRIPTION

The MP2664 is a highly integrated, single-cell, Li-ion/Li-polymer battery charger with system power path management for space-limited, portable applications. The MP2664 uses input power from either an AC adapter or a USB port to supply the system load and charge the battery independently. The charger features constant current pre-charge, constant current fast-charge (CC) and constant voltage (CV) regulation, charge termination, and charge status.

The power path management function ensures continuous power to the system by automatically selecting the input, the battery, or both to power the system. This power stage features a low dropout regulator from the input to the system and a 100mΩ switch from the battery to the system. Power path management separates the charging current from the system load, which allows for proper charge termination and keeps the battery in full-charge mode.

The MP2664 provides system short-circuit protection (SCP) by limiting the current from the input to the system and the battery to the system. This feature is especially critical for preventing the Li-ion battery from being damaged by excessively high currents. An on-chip battery under-voltage lockout (UVLO) cuts off the path between the battery and the system if the battery voltage drops below the programmable battery UVLO threshold, which prevents the Li-ion battery from being over-discharged. An integrated I²C control interface allows the MP2664 to program the charging parameters, such as input current limit, input voltage regulation limit, charging current, battery regulation voltage, safety timer, and battery UVLO.

The MP2664 is available in a QFN-10 (2mmx2mm) package.

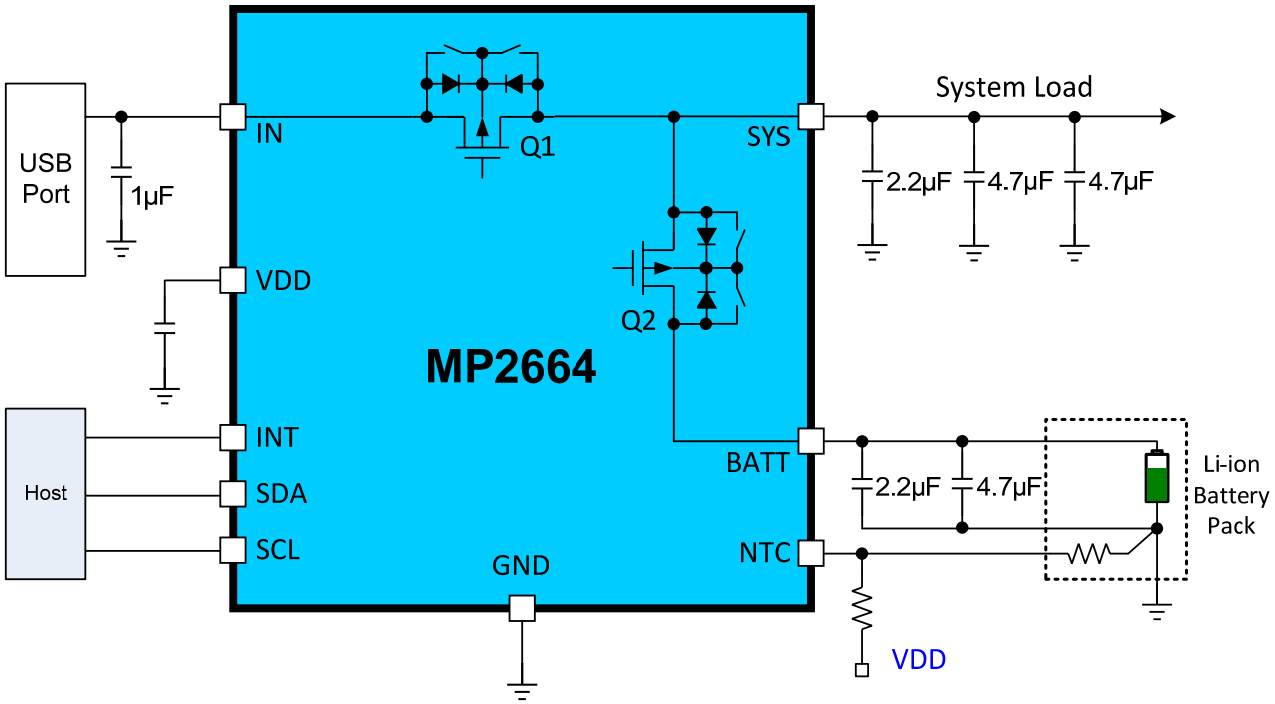
FEATURES

- Fully Autonomous Charger for Single-Cell Li-Ion/Li-Polymer Batteries
- Complete Power Path Management for Simultaneously Powering the System and Charging the Battery
- ±0.5% Charging Voltage Accuracy
- 13V Maximum Voltage for the Input Source
- I²C Interface for Setting Charging Parameters and Status Reporting
- Fully Integrated Power Switches and No External Blocking Diode Required
- Built-In Robust Charging Protection Including Battery Temperature Monitoring and Programmable Timer
- PCB Over-Temperature Protection (OTP)
- System Reset Function
- Built-In Battery Disconnection Function
- Thermal Limiting Regulation On-Chip
- Available in a QFN-10 (2mmx2mm) Package

APPLICATIONS

- Wearable Devices
- Smart Handheld Devices
- Fitness Accessories
- Smart Watches

TYPICAL APPLICATION



ORDERING INFORMATION

Part Number*	Package	Top Marking
MP2664GG-xxxx**	QFN-10 (2mmx2mm)	*See Below*
EVKT-MP2664	Evaluation Kit	*See Below*

* For Tape & Reel, add suffix –Z (e.g.: MP2664GG-xxxx–Z).

**"xxxx" is the register setting option. The factory default is "0000." This content can be viewed in the I²C register map. Please contact an MPS FAE to obtain an "xxxx" value.

TOP MARKING

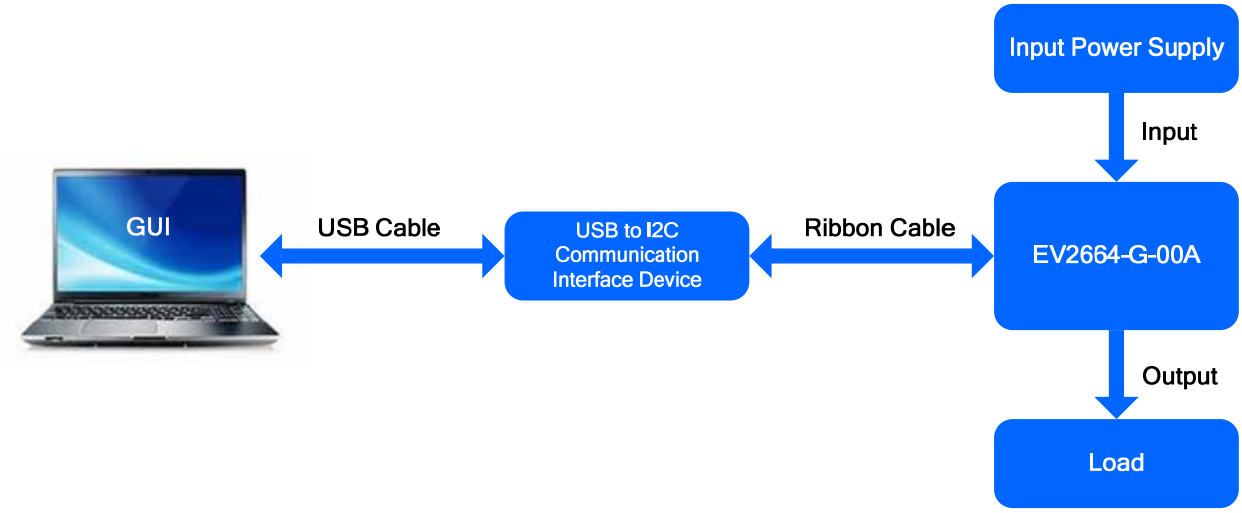
HVY
LLL

HV: Product code of MP2664GG
Y: Year code
LLL: Lot number

EVALUATION KIT EVKT-MP2664

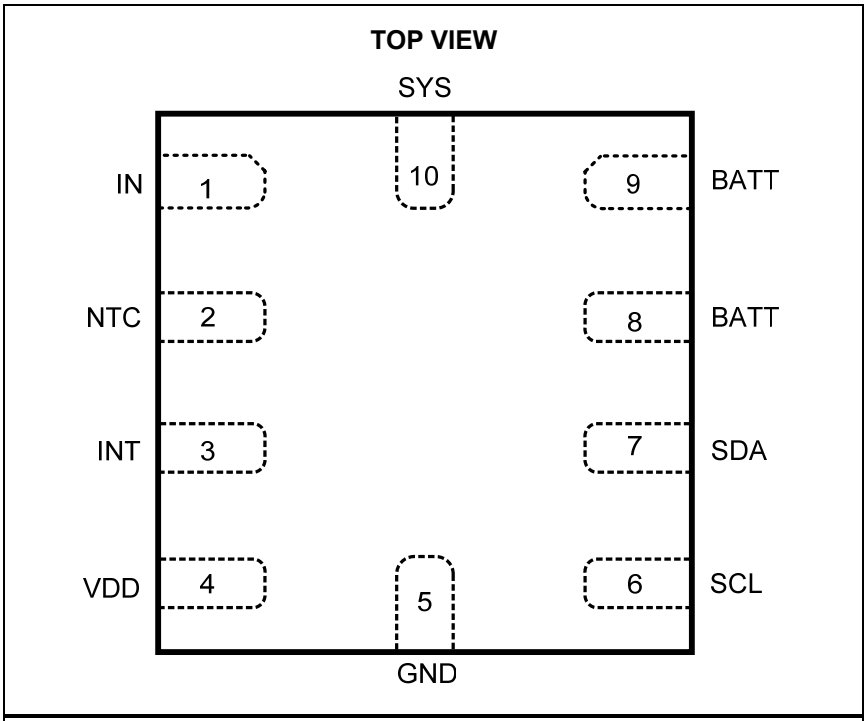
EVKT-MP2664 Kit contents: (Items below can be ordered separately)

#	Part Number	Item	Quantity
1	EV2664-G-00A	MP2664 evaluation board	1
2	EVKT-USBI2C-02-Bag	Includes one USB to I2C communication interface device, one USB cable, one ribbon cable	1
3	Online resources	Includes: Datasheet, User guide, Product brief, and GUI	1



EVKT-MP2664 Evaluation Kit Set-Up

PACKAGE REFERENCE



QFN-10 (2mmx2mm)

PIN FUNCTIONS

Package Pin #	Name	I/O	Description
1	IN	Power	**Input power.** Place a ≥1μF ceramic capacitor from IN to GND as close to the IC as possible.
2	NTC	I	**Temperature sense input.** Connect a negative temperature coefficient thermistor to NTC. Program the hot and cold temperature window with a resistor divider from VDD to NTC to GND. The charge is suspended when NTC is out of range.
3	INT	O	**Open-drain interrupt output.** INT can send the charging status and fault interruption to the host. INT is also used to disconnect the system from the battery. Pull INT from high to low for >16s.The battery MOSFET is off and turns on automatically after >4s regardless of the INT state. The external pull-up resistor at INT should *not* be smaller than 300kΩ.
4	VDD	I	**Internal control power supply.** Connect a 0.1μF ceramic capacitor from VDD to GND. No external load is allowed.
5	GND	Power	**Ground.**
6	SCL	I/O	**I²C interface clock.** Connect SCL to the logic rail through a 10kΩ resistor.
7	SDA	I/O	**I²C interface data.** Connect SDA to the logic rail through a 10kΩ resistor.
8, 9	BATT	Power	**Battery.** Place a ceramic capacitor from BATT to GND as close to the IC as possible.
10	SYS	Power	**System power supply.** Place a ceramic capacitor from SYS to GND as close to the IC as possible.

ABSOLUTE MAXIMUM RATINGS (1)

V_{IN} ..... -0.3V to +13V
All other pins to GND ..... -0.3V to +6.0V
Continuous power dissipation (T_A = +25°C) (2)
..... 1.25W
Junction temperature ..... 150°C
Lead temperature (solder) ..... 260°C
Storage temperature ..... -65°C to +150°C

Recommended Operating Conditions (3)

Supply voltage (V_{IN}) ..... 4.35V to 5.5V (USB input)
I_{IN} ..... Up to 455mA
I_{SYS} ..... Up to 3A (5)
I_{CHG} ..... Up to 455mA
V_{BATT} ..... Up to 4.545V
Operating junction temp. (T_J) .... -40°C to +125°C

Thermal Resistance (4) θ_{JA} θ_{JC}

QFN-10 (2mmx2mm)	80	16	°C/W

NOTES:

1) Exceeding these ratings may damage the device.
2) The maximum allowable power dissipation is a function of the maximum junction temperature T_J (MAX), the junction-to-ambient thermal resistance θ_{JA}, and the ambient temperature T_A. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P_D (MAX) = (T_J (MAX)-T_A)/θ_{JA}. Exceeding the maximum allowable power dissipation produces an excessive die temperature, causing the regulator to go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
3) The device is not guaranteed to function outside of its operating conditions.
4) Measured on JESD51-7, 4-layer PCB.
5) Guaranteed by design

ELECTRICAL CHARACTERISTICS

V_{IN} = 5.0V, V_{BATT} = 3.5V, T_A = +25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Units
Input Source and Battery Protection						
Input operation voltage	V_{IN}		4.35	5	5.5	V
Battery input voltage (6)	V_{BATT}				4.5	V
Input over-voltage protection trigger threshold	V_{IN_OVP}	Input rising threshold	5.85	6	6.15	V
Input over-voltage protection recover threshold				350		mV
Input under-voltage lockout threshold	V_{IN_UVLO}	Input rising threshold	3.8	3.9	4.0	V
Input under-voltage lockout threshold hysteresis				170		mV
Input vs. battery voltage headroom threshold	V_{HDRM}	Input rising vs. battery	100	130	160	mV
Input vs. battery voltage headroom threshold hysteresis				85		mV
Battery under-voltage lockout threshold	V_{BATT_UVLO}	I²C programmable range	2.4		3.1	V
		Falling, programmable, Reg01 bit[2:0] = 100	2.6	2.8	3.0	V
Battery under-voltage threshold hysteresis				210		mV
Battery over-voltage protection threshold	V_{BATT_OVP}	Rising, higher than V_{BATT_REG}		130		mV
Battery over-voltage protection hysteresis				70		
Power Path Management						
System regulation voltage	V_{SYS_REG}	V_{IN} = 5.5V, I_{SYS} = 10mA, I_{CHG} = 0A	4.55	4.65	4.75	V
Input current limit	I_{IN_LIM}	Reg00 bit[2:0] = 000 - 85mA	65	75	85	mA
		Reg00 bit[2:0] = 001 - 130mA	102	116	130	
		Reg00 bit[2:0] = 100 - 265mA	230	247	265	
		Reg00 bit[2:0] = 111 - 455mA	400	428	455	
Input minimum voltage regulation	V_{IN_MIN}	I²C programmable range	3.88		5.08	V
		I²C setting V_{IN_MIN} = 4.20V	4.10	4.20	4.30	
IN to SYS switch on resistance	R_{ON_Q1}	V_{IN} = 5V, I_{SYS} = 100mA		300	400	mΩ
Input quiescent current	I_{IN_Q}	V_{IN} = 5.5V, CE = L, charge enabled, I_{CHG} = 0A, I_{SYS} = 0A		630		µA
		V_{IN} = 5.5V, CE = H, charge disabled		500		

ELECTRICAL CHARACTERISTICS *(continued)*

V_{IN} = 5.0V, V_{BATT} = 3.5V, T_A = +25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Units
Battery quiescent current	I_{BATT_Q}	V_{IN} = 5V, CE = L, I_{SYS} = 0A, V_{BATT} = 4.3V		32		μA
		V_{IN} = 0V, CE = H, I_{SYS} = 0A, V_{BATT} = 4.35V, disable PCB OTP function, do not include the current from external NTC resistor		11	13	
		V_{IN} = 0V, CE = H, I_{SYS} = 0A, V_{BATT} = 4.35V, enable PCB OTP function, do not include the current from external NTC resistor		20	24	
		V_{BATT} = 4.5V, V_{IN} = V_{SYS} = GND, FET_DIS = 1, shipping mode		4	5.5	
Battery MOSFET on resistance	R_{ON_Q2}	V_{IN} < 2V, V_{BATT} = 3.5V, I_{SYS} = 100mA		100	150	mΩ
Battery current regulation in discharge mode	I_{DSCHG}	I²C programmable range	400		3200 (6)	mA
Battery MOSFET switch leakage		V_{BATT} = 4.5V, V_{IN} = V_{SYS} = GND, disconnect mode			1	μA
SYS reverse to BATT switch leakage		V_{SYS} = 6V, V_{IN} = 4.5V, V_{BATT} = GND, CE = H			1	μA
Battery MOSFET disconnect by INT (6)	t_{INT}	INT pull-low lasting time to turn off the battery MOSFET		16		s
		Battery FET off lasting time before turn-on		4		
Battery Charger						
Battery charge voltage regulation	V_{BATT_REG}	I²C programmable range	3.600		4.545	V
		Reg04 bit[7:2] = 101000	4.179	4.20	4.221	
		Reg04 bit[7:2] = 110010	4.328	4.35	4.372	
Fast charge current	I_{CC}	V_{IN} = 5V, V_{BATT} = 3.8V, I²C programmable range	8		535 (6)	mA
		V_{IN} = 5V, V_{BATT} = 3.8V, $I_{CC\_SETTING}$ = 93mA	88	93	98	
		V_{IN} = 5V, V_{BATT} = 3.8V, $I_{CC\_SETTING}$ = 246mA	232	248	263	
		V_{IN} = 5V, V_{BATT} = 3.8V, $I_{CC\_SETTING}$ = 399mA	376	401	440	
Junction temperature regulation (6)	T_{J_REG}	Reg06 bit[1:0] = 11 - 120°C		120		°C

ELECTRICAL CHARACTERISTICS *(continued)*

V_{IN} = 5.0V, V_{BATT}=3.5V, T_A = +25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Units
Pre-charge current	I_{PRE}	I²C programmable range	6		27	mA
		$I_{PRE\_SETTING}$ = 6mA, Reg03 bit[1:0] = 00	2.5	4.7		
		$I_{PRE\_SETTING}$ = 20mA, Reg03 bit[1:0] = 10	14	18	22	
Charge termination current threshold	I_{TERM}	$I_{CC\_SETTING}$ ≤ 263mA, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 00	5	7	9	mA
		$I_{CC\_SETTING}$ ≤ 263mA, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 01	10	13.5	17	
		$I_{CC\_SETTING}$ ≤ 263mA, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 10	16	20	24	
		$I_{CC\_SETTING}$ ≤ 263mA, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 11	22	27	32	
		$I_{CC\_SETTING}$ ≤ 280mA, (Reg02 bit[4] = 1), Reg03 bit[1:0] = 00	10	13.5	17	
		$I_{CC\_SETTING}$ ≤ 280mA, (Reg02 bit[4] = 1), Reg03 bit[1:0] = 01	22	27	32	
		$I_{CC\_SETTING}$ ≤ 280mA, (Reg02 bit[4] = 1), Reg03 bit[1:0] = 10	34	42	49	
		$I_{CC\_SETTING}$ ≤ 280mA, (Reg02 bit[4] = 1), Reg03 bit[1:0] = 11	46	55	64	
Charge termination current threshold hysteresis	I_{TERM_HYS}	$I_{CC\_SETTING}$ ≤ 263mA, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 10	7.5	11	15	mA
		$I_{CC\_SETTING}$ ≤ 280mA, (Reg02 bit[4] = 0), Reg03 bit[1:0] = 10	19	25	31	
Pre-charge to fast charge threshold	V_{BATT_PRE}	V_{BATT} rising, set V_{BATT_PRE} = 3.0V	2.8	3.0	3.1	V
Pre-charge to fast charge threshold hysteresis				90		mV
Auto-recharge battery voltage threshold	V_{RECH}	Reg04 bit[0] = 0	120	160	200	mV
		Reg04 bit[0] = 1	260	300	365	
Thermal Protection						
Thermal shutdown threshold (6)	T_{J_SHDN}	Rising		150		°C
Thermal shutdown hysteresis (6)				20		°C
NTC output current	I_{NTC}	CE = L, NTC = 3V	-100	0	100	nA
NTC cold temperature rising threshold	V_{COLD}	As a percentage of V_{DD}	63	65	67	%
NTC cold temperature rising threshold hysteresis				30		mV

ELECTRICAL CHARACTERISTICS *(continued)*

V_{IN} = 5V, T_A = 25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Units
NTC hot temperature falling threshold	V_{HOT}	As a percentage of V_{DD}	31	33	35	%
NTC hot temperature falling threshold hysteresis				70		mV
NTC hot temperature falling threshold for PCB OTP	V_{HOT_PCB}	As a percentage of V_{DD}	30	32	34	%
NTC hot temperature falling threshold hysteresis for PCB OTP				85		mV
Logic I/O Pin Characteristics (6)						
Low logic voltage threshold	V_L				0.4	V
High logic voltage threshold	V_H		1.3			V
I²C Interface (SDA, SCL) (6)						
Input high voltage level	V_{IH}	V_{PULL_UP} = 1.8V, SDA and SCL	1.3			V
Input low voltage level	V_{IL}	V_{PULL_UP} = 1.8V, SDA and SCL			0.4	V
Output low voltage level	V_{OL}	I_{SINK} = 5mA			0.4	V
I²C clock frequency	F_{SCL}				400	kHz
Clock Frequency and Watchdog Timer						
Clock frequency	F_{CLK}			32		kHz
Watchdog timer	t_{WDT}	Programmable (Reg05 bit[5:4] = 11)		160		s

NOTE:

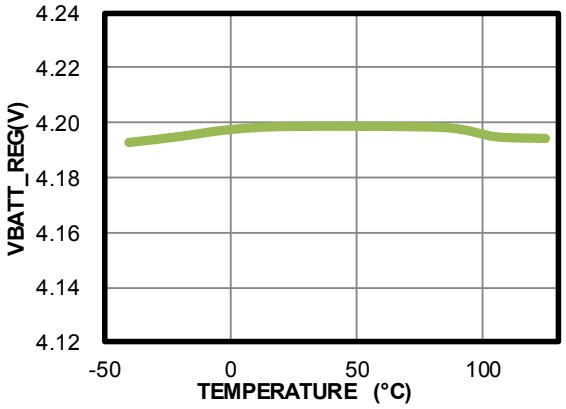
6) Guaranteed by design.

TYPICAL PERFORMANCE CHARACTERISTICS

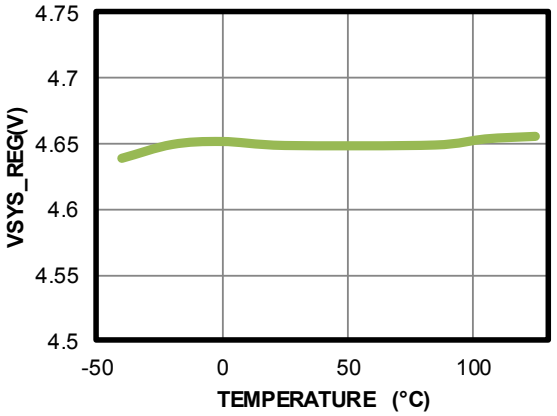
V_{IN} = 5V, T_A = 25°C, I_{IN_LIM} = 455mA, I_{CC} = 246mA, V_{IN_MIN} = 4.6V, unless otherwise noted.

Battery Regulation Voltage vs. Temperature

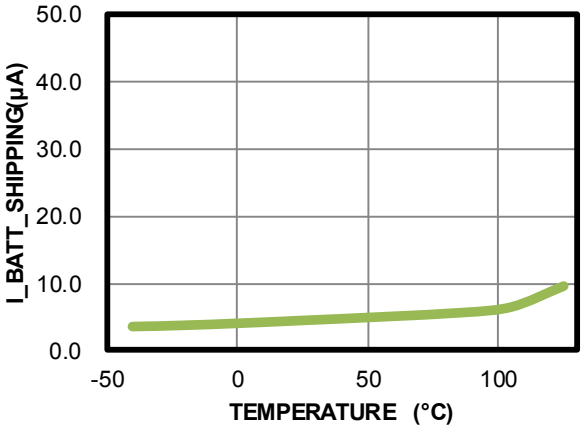
V_{BATT_REG} = 4.2V



System Regulation Voltage vs. Temperature

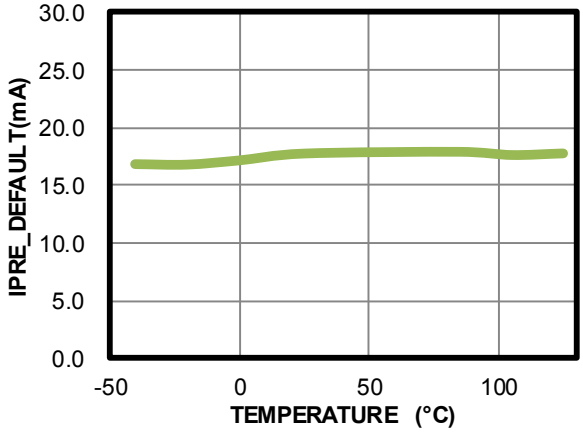


Battery Current under Shipping Mode vs. Temperature



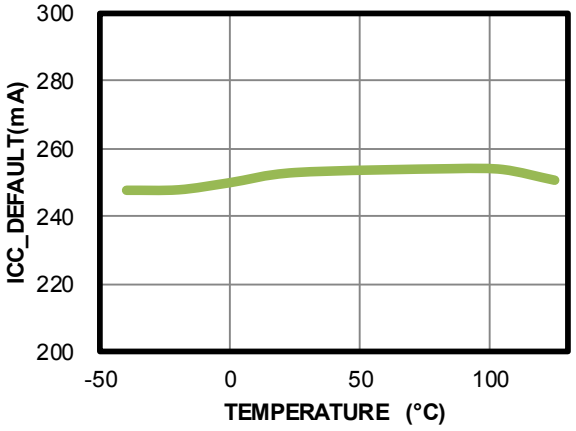
Pre-Charge Current vs. Temperature

I_{PRE} = 20mA



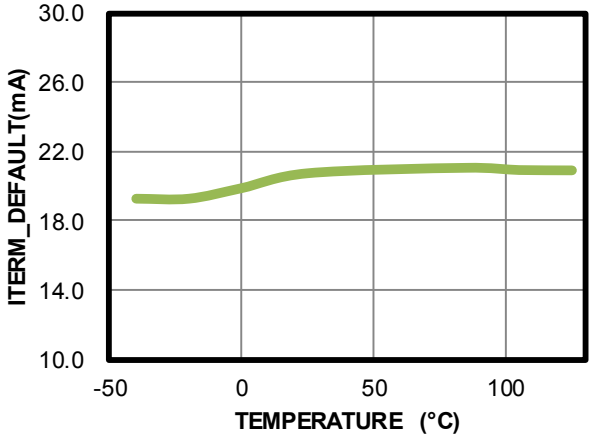
CC Charge Current vs. Temperature

I_{CC} = 246mA



Battery Termination Current vs. Temperature

I_{TERM} = 20mA

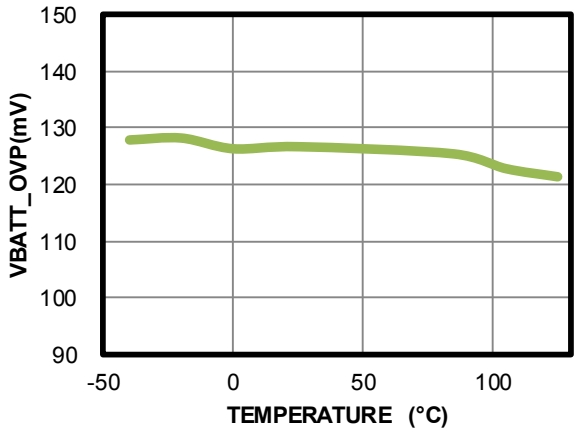


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, T_A = 25°C, I_{IN_LIM} = 455mA, I_{CC} = 246mA, V_{IN_MIN} = 4.6V, unless otherwise noted.

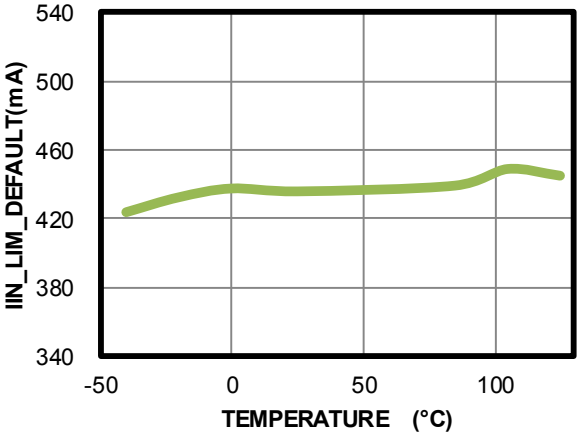
Battery OVP Voltage vs. Temperature

Higher than V_{BATT_REG}



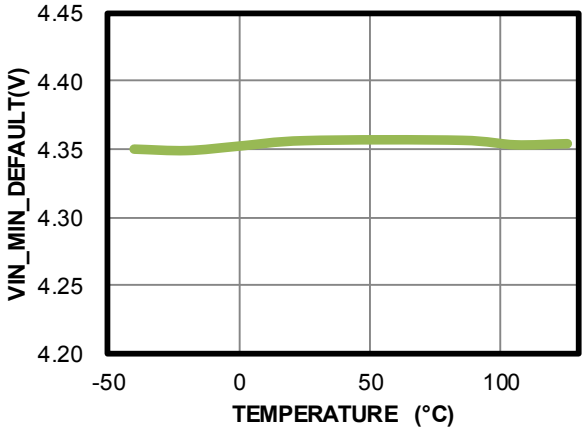
Input Current Limit vs. Temperature

I_{IN_LIM} = 455mA



Input Minimum Voltage vs. Temperature

V_{IN_MIN} = 4.36V

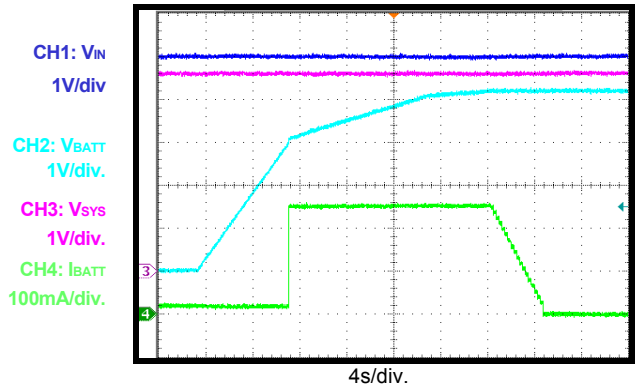


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, T_A = 25°C, I_{IN_LIM} = 455mA, I_{CC} = 246mA, V_{IN_MIN} = 4.6V, unless otherwise noted.

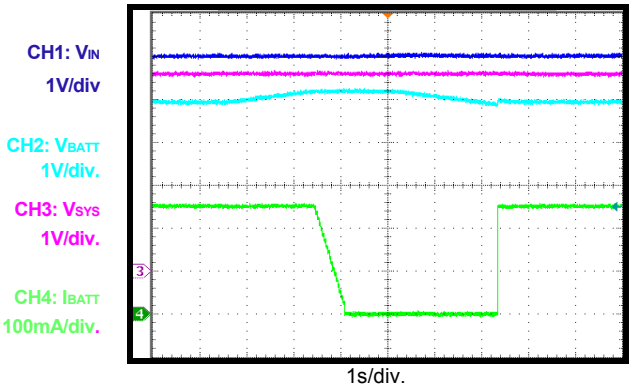
Battery Charge Curve

I_{SYS} = 0A



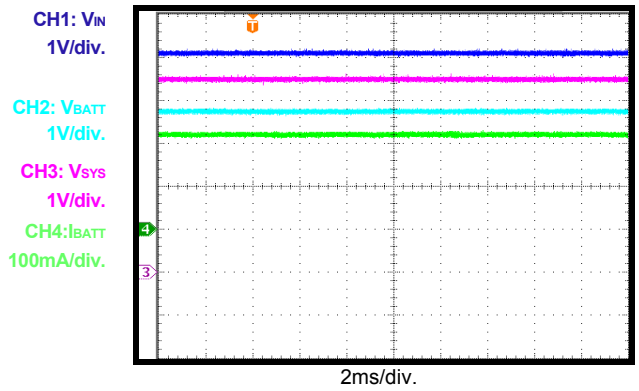
Auto-Recharge

I_{SYS} = 0A



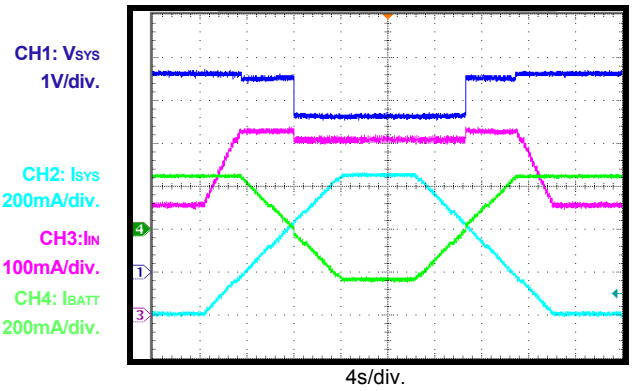
CC Charge Steady State

V_{BATT} = 3.7V, I_{SYS} = 200mA



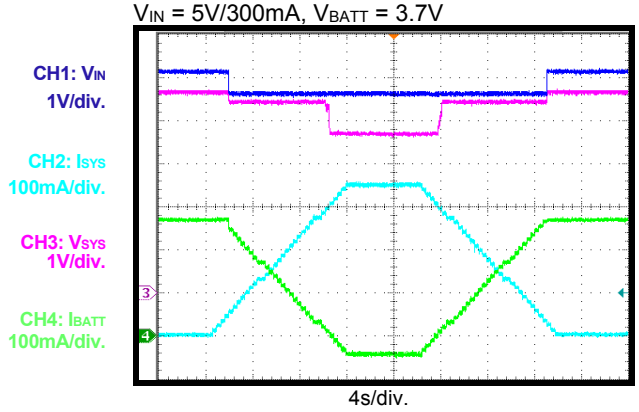
Input Current Limit-Based PPM

V_{BATT} = 3.7V



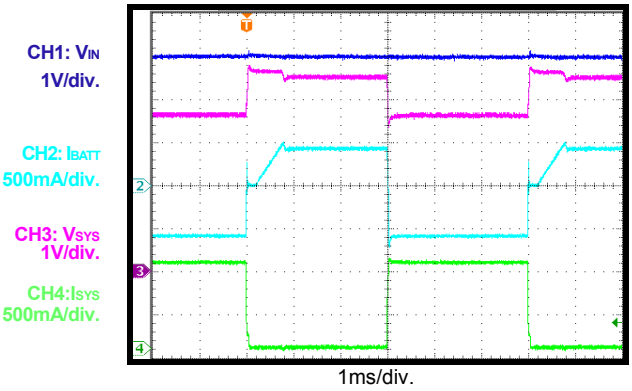
Input Voltage Regulation-Based PPM

V_{IN} = 5V/300mA, V_{BATT} = 3.7V



SYS Load Transient

V_{IN} = 5V, V_{BATT} = 3.7V, I_{CC} = 535mA, I_{SYS} = 0 - 1A

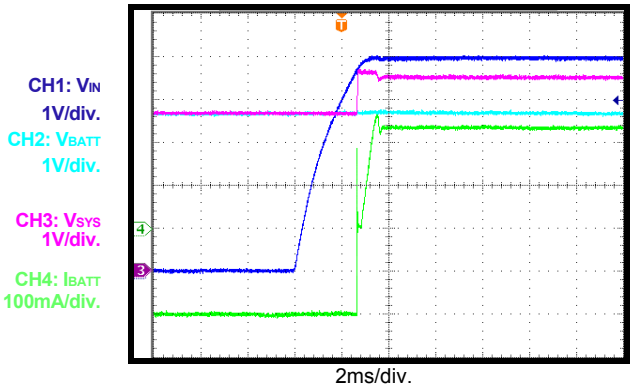


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, T_A = 25°C, I_{IN_LIM} = 455mA, I_{CC} = 246mA, V_{IN_MIN} = 4.6V, unless otherwise noted.

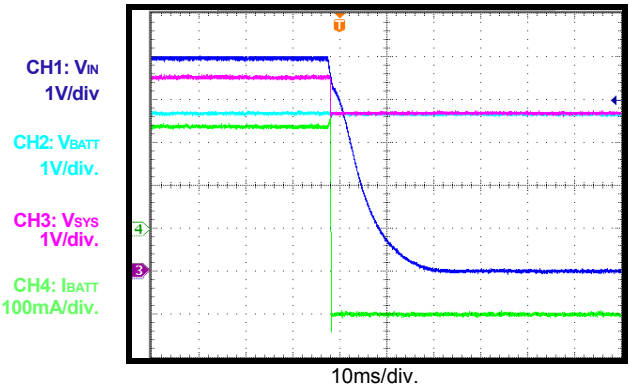
Power On

V_{BATT} = 3.7V, I_{SYS} = 200mA



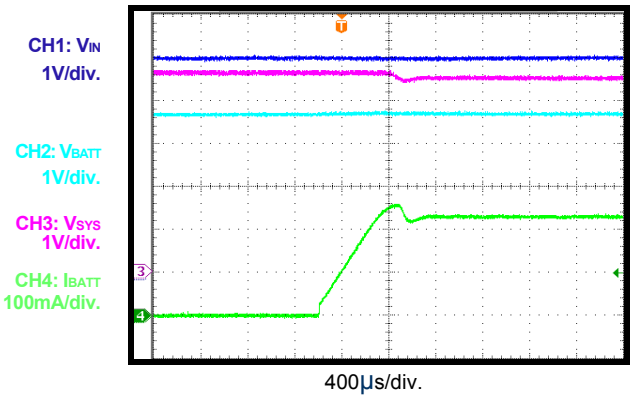
Power Off

V_{BATT} = 3.7V, I_{SYS} = 200mA



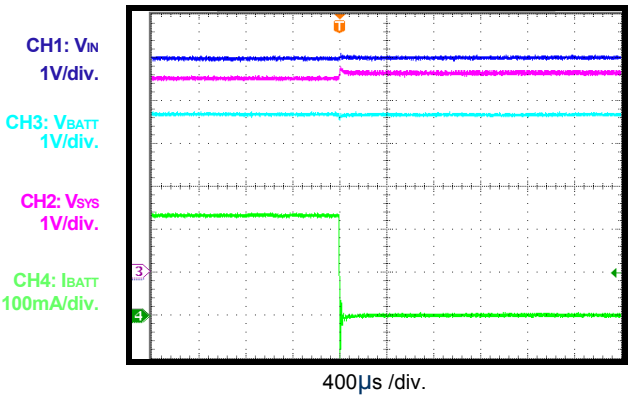
Charge Enable

V_{BATT} = 3.7V, I_{SYS} = 200mA



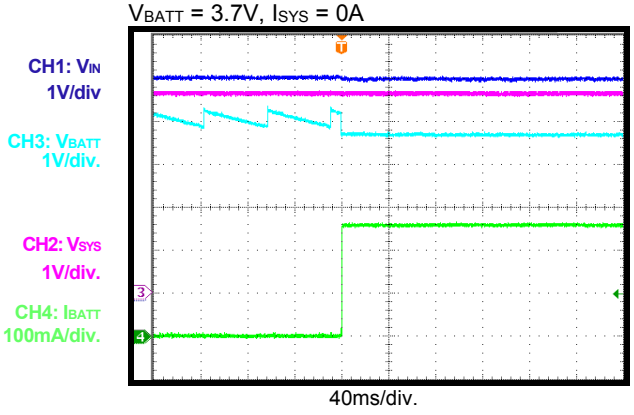
Charge Disable

V_{BATT} = 3.7V, I_{SYS} = 200mA



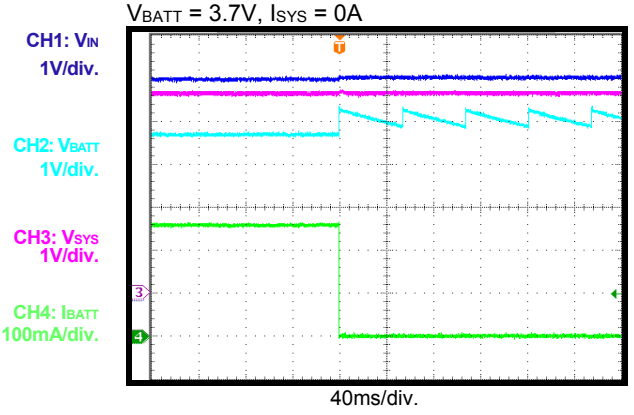
BATT Insertion

V_{BATT} = 3.7V, I_{SYS} = 0A



BATT Removal

V_{BATT} = 3.7V, I_{SYS} = 0A

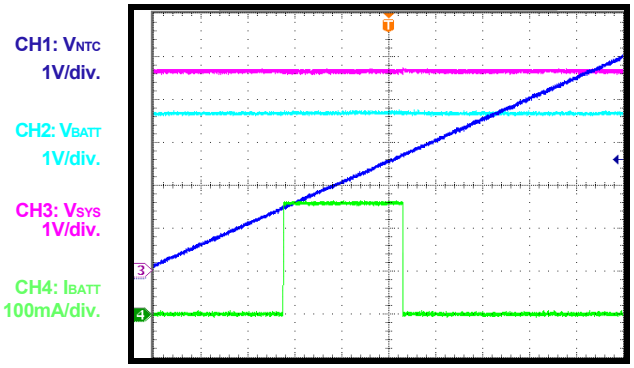


TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

V_{IN} = 5V, T_A = 25°C, I_{IN_LIM} = 455mA, I_{CC} = 246mA, V_{IN_MIN} = 4.6V, unless otherwise noted.

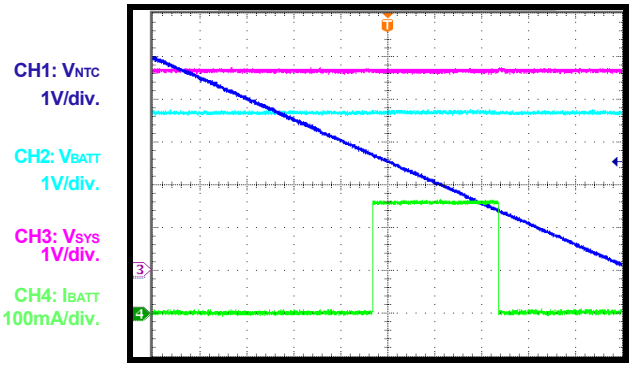
NTC Rising

V_{BATT} = 3.7V, I_{SYS} = 0A, PCB OTP disable



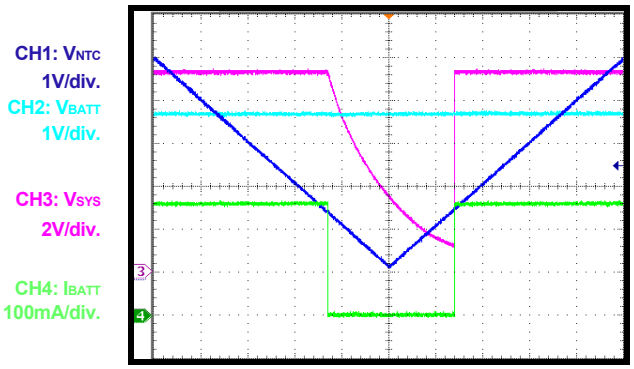
NTC Falling

V_{BATT} = 3.7V, I_{SYS} = 0A, PCB OTP disable



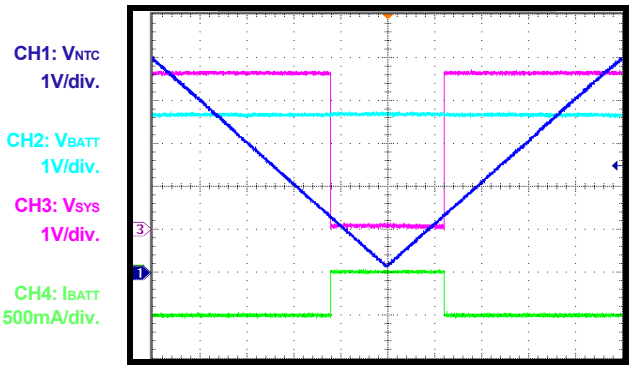
PCB OTP @ Charge Mode

V_{BATT} = 3.7V, I_{SYS} = 0A



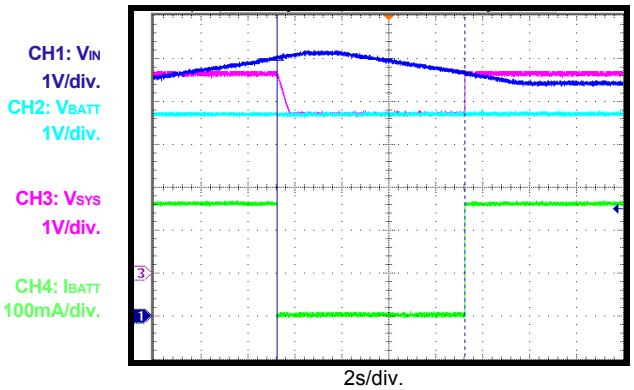
PCB OTP @ Discharge Mode

V_{IN} = 0V, V_{BATT} = 3.7V, I_{SYS} = 500mA



V_{IN} OVP Operation

V_{BATT} = 3.7V, I_{SYS} = 0A



BLOCK DIAGRAM

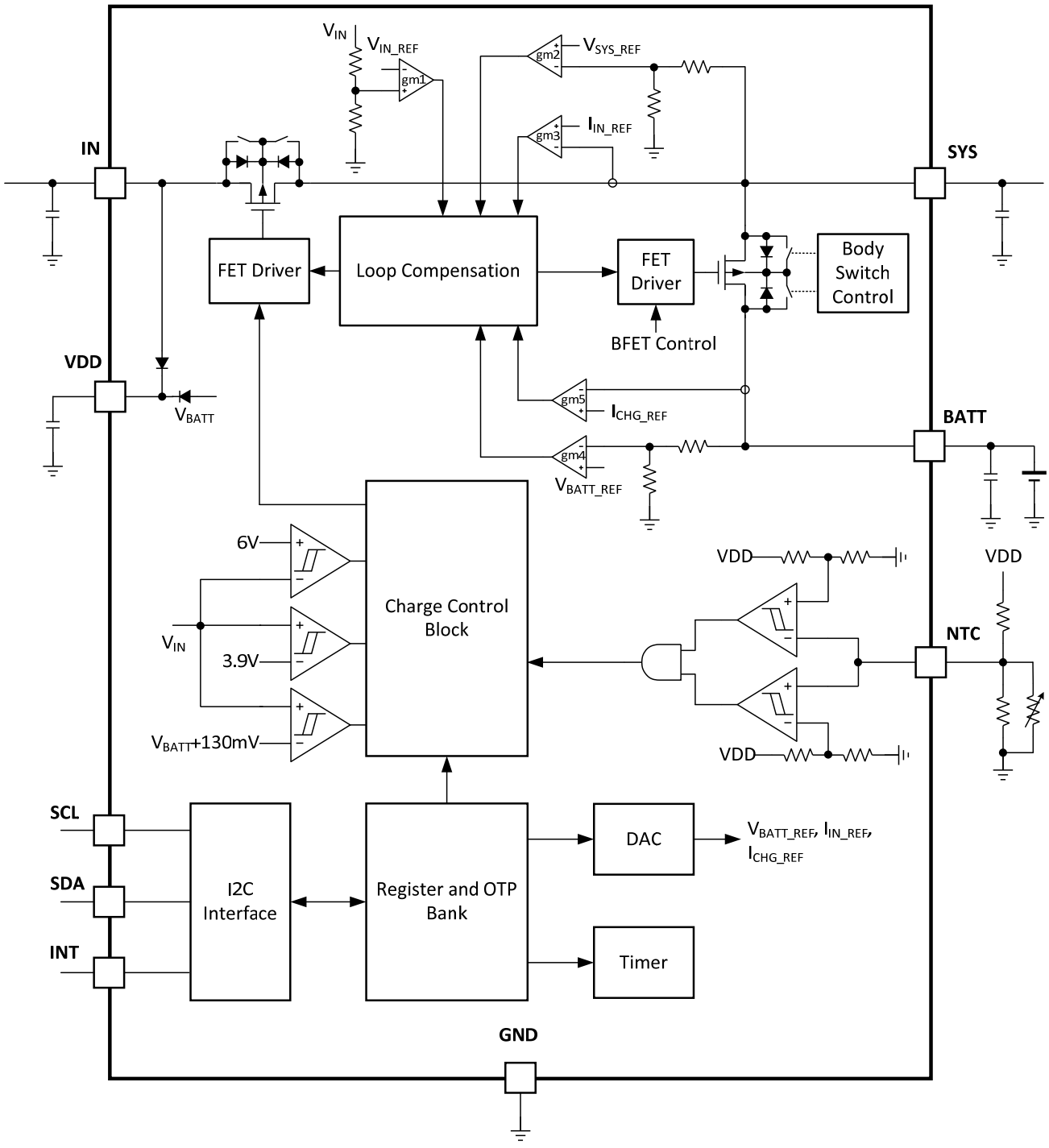


Figure 1: Function Block Diagram

OPERATION

The MP2664 is an I²C-controlled, single-cell, Li-ion or Li-polymer battery charger with complete power path management. The full-charge function features constant current pre-charge (PRE.C), constant current fast-charge (CC) and constant voltage (CV) regulation, charge termination, auto-recharge, and a built-in timer. The power path function allows the input source to power the system and charge the battery simultaneously. If there is a conflict in meeting both the system load and battery charging current, the IC reduces the charging current automatically or uses the battery as a supplemental power to satisfy the system load.

The IC integrates a 300mΩ LDO MOSFET between IN and SYS and a 100mΩ battery MOSFET between SYS and BATT.

In charging mode, the on-chip 100mΩ battery MOSFET works as a full-featured linear charger with constant current pre-charging, constant current fast-charging and constant-voltage charging, charge termination, auto-recharging, NTC monitoring, built-in timer control, and thermal protection. The charge current can be programmed via the I²C interface. The IC limits the charge current when the die temperature exceeds the thermal regulation threshold (120°C default).

In supplement mode, the 100mΩ battery MOSFET is fully turned on to connect the battery to the system load when the input power is not enough to power the system load. When the input is removed, the 100mΩ battery MOSFET is also fully turned on, allowing the battery to power up the system.

When the system load is satisfied, the remaining current is used to charge the smart power path management battery. The IC reduces the charging current or uses power from the battery to satisfy the system load when its demand is over the input power capacity.

Figure 2 shows the power path management structure of the MP2664.

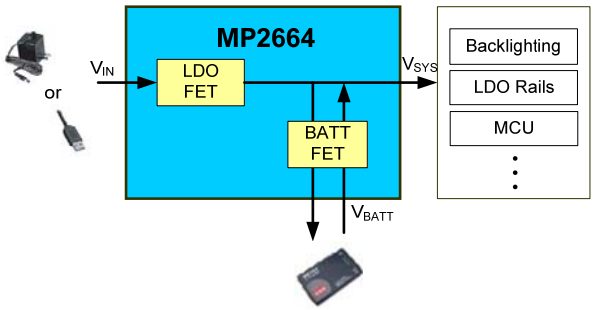


Figure 2: Power Path Management Structure

Power Supply

The internal bias circuit of the IC is powered from the higher voltage of IN or BATT. When IN or BATT rises above the respective under-voltage lockout (UVLO) threshold, the sleep comparator, battery depletion comparator, and the battery MOSFET driver are active. The I²C interface is ready for communication, and all registers are reset to the default value. The host can access all registers.

Input OVP and UVLO

The MP2664 has an input over-voltage protection (OVP) threshold and an input UVLO threshold. Once the input voltage exits the normal input voltage range, the Q1 MOSFET is turned off immediately.

When the input voltage is identified as a good source, a 200µs immunity timer becomes active. If the input power is still sufficient until the 200µs timer expires, the system starts up. Otherwise, Q1 remains off.

Figure 3 depicts the operation profile.

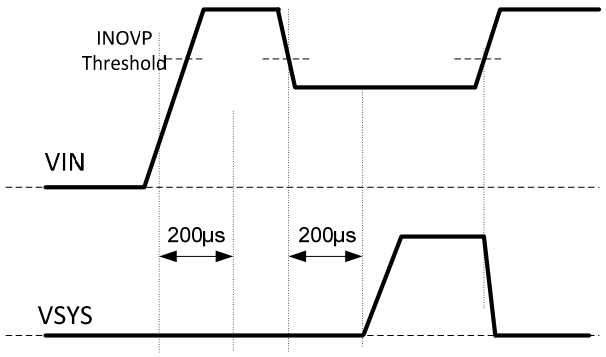


Figure 3: Input Power Detection Operation Profile

Power Path Management

The IC employs a direct power path structure with the battery MOSFET decoupling the system from the battery, which allows for separate control between the system and the battery. The system is given priority to start up

even with a deeply discharged or missing battery. When the input power is available, even with a depleted battery, the system voltage is always regulated to V_{SYS_REG} by the integrated LDO MOSFET.

As shown in Figure 2, the direct power structure is composed of a frond-end LDO MOSFET between IN and SYS and a battery MOSFET between SYS and BATT. The LDO MOSFET and battery MOSFET can be controlled by I²C.

Table 1: MOSFET Control by I²C

MOSFET On/Off Changed By Control	Hi-Z Mode and Charge Control	
	Set EN_HIZ to 1	Set CEB to 1
LDO FET	OFF	x
Battery FET (charging)	x	OFF
Battery FET (discharging)	x	x

NOTE: x indicates that the value does not matter.

The input LDO (using an LDO MOSFET) provides power to the system, which drives the system load directly and charges the battery through the battery MOSFET.

For the system voltage control, when the input voltage is higher than V_{SYS_REG}, the system voltage is regulated to V_{SYS_REG}. When the input voltage is lower than V_{SYS_REG}, the LDO MOSFET is fully on with the input current limit.

Battery Charge Profile

The IC provides three main charging phases: constant current pre-charge, constant current fast-charge, and constant-voltage charge (see Figure 4).

1. Phase 1 (constant current pre-charge): The IC is able to pre-charge the deeply depleted battery safely until the battery voltage reaches the pre-charge to the fast-charge threshold (V_{BATT_PRE}). The pre-charge current is programmable via Reg03 bit[1:0]. If V_{BATT_PRE} is not reached before the pre-charge timer (1hr) expires, the charge cycle is stopped, and a corresponding timeout fault signal is asserted.
2. Phase 2 (constant current fast charge): When the battery voltage exceeds V_{BATT_PRE}, the IC enters a constant current fast-charge phase. The fast-charge current can be programmable via Reg02 bit[4:0].
3. Phase 3 (constant-voltage charge): When the battery voltage rises to the pre-programmable charge full voltage (V_{BATT_REG}) set via Reg04 bit[7:2], the charge mode changes from CC mode to CV mode, and the charge current begins to taper off.

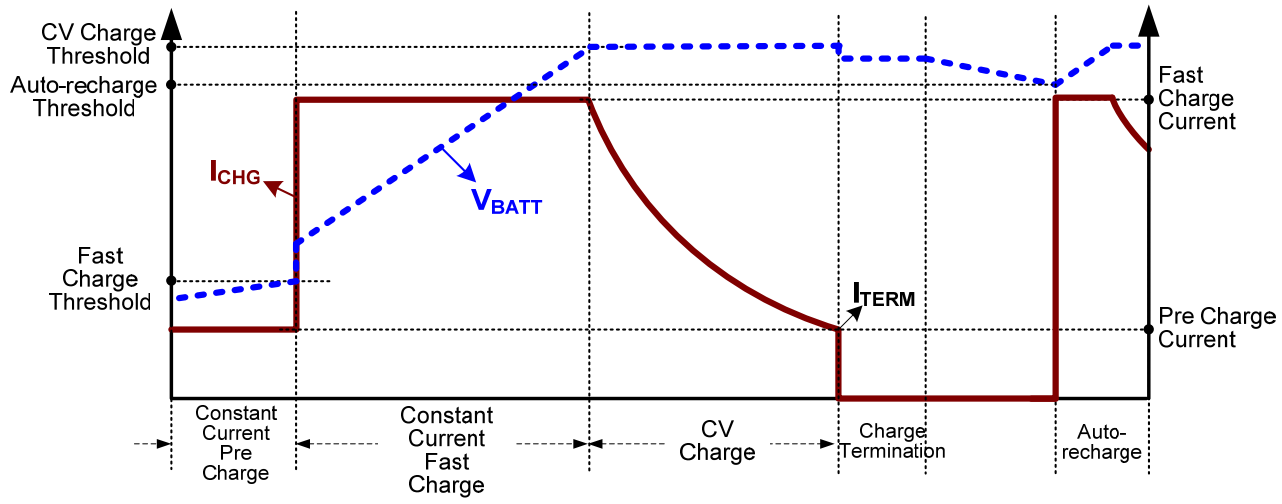


Figure 4: Battery Charge Profile

Assuming that the termination function (EN_TERM) is set via Reg05 bit[6] = 1, the charge cycle is considered to be complete when the following conditions are valid:

- The charge current (I_{CHG}) reaches the end of charge (EOC) current threshold (I_{TERM}), and the 2.5ms delay timer is initiated.
- During the 2.5ms delay period, I_{BATT} is always smaller than I_{TERM} + I_{TERM_HYS}.

The charge status is marked as complete once the 2.5ms delay timer expires.

The charge current is terminated at the same time if TERM_TMR is set via Reg05 [0] = 0; otherwise, the charge current continues tapering off.

If EN_TERM = 0, the termination function is disabled, and the above actions will not occur (see Table 2).

Table 2: Termination Function Selection Table

EN_TERM	TERM_TMR	After I_{BATT} hit I_{TERM} in CV mode	
		Operation	Charge Status
0	x	Keep CV charge	Charge
1	0	Charge done	Charge done
1	1	Keep CV charge	Charge done

NOTE: x indicates that the value does not matter.

During the charging process, the actual charge current may be less than the register setting due to other loop regulations, such as dynamic power management (DPM) regulation (input voltage, input current) or thermal regulation. If the input current or the input voltage reach their limits during the CV charge, the charge-full termination is not influenced when the charge current is not as close to the EOC current specification.

A new charge cycle starts when the following conditions are valid:

- The input power is recycled
- Battery charging is enabled by the I²C
- Auto-recharge kicks in

Under the following conditions:

- No thermistor fault at NTC
- No safety timer fault
- No battery over-voltage
- BATT FET is not forced to turn off

Automatic Recharge

When the battery is fully charged and the charging is terminated, the battery may be discharged due to system consumption or self-discharge. When the battery voltage is discharged below the recharge threshold and V_{IN} is still in the operation range, the IC begins another new charging cycle automatically without having to restart the charging cycle manually.

The auto-recharge function is valid only when EN_TERM = 1 and TERM_TMR = 0.

Battery Over-Voltage Protection (OVP)

The IC is designed with a built-in battery over-voltage limit about 130mV higher than V_{BATT_REG}. When a battery over-voltage event occurs, the IC suspends the charging immediately and asserts a fault.

Input Current and Input Voltage-Based Power Management

To meet the input source (usually USB) maximum current-limit specification, the IC uses input current-based power management by monitoring the input current continuously. The total input current limit can be programmed via the I²C to prevent the input source from overloading.

If the pre-set input current limit is higher than the rating of the input source, back-up input voltage-based power management also works to prevent the input source from being overloaded. If either the input current limit or the input voltage limit is reached, the Q1 MOSFET between IN and SYS are regulated so that the total input power is limited. As a result, the system voltage drops. Once the system declines to the minimum value of 4.56V or V_{IN} - 160mV, the charge current is reduced to prevent the system voltage from dropping further.

Voltage-based DPM regulates the input voltage to V_{IN_MIN} when the load is over the input power capacity. V_{IN_MIN} set via the I²C should be at least 400mV higher than V_{BATT_REG} to ensure the stable operation of the regulator.

Battery Supplement Mode

The charge current is reduced to keep the input current or input voltage in regulation when DPM occurs. If the charge current is at zero, and the input source is still overloaded due to a heavy system load, the system voltage starts to fall off. Once the system voltage falls below the battery voltage, the IC enters battery supplement mode. When the system voltage is 30mV below the battery voltage, ideal diode mode is enabled. The battery MOSFET is regulated to maintain V_{BATT} - V_{SYS} at 22.5mV. If the supplement current I_{DSCHG} * R_{ON_BATT} is higher than 22.5mV, the battery MOSFET is fully turned on to keep the ideal forward voltage. When the system load decreases, once V_{SYS} is higher than V_{BATT} + 20mV, ideal diode mode is disabled.

Figure 5 shows the dynamic power management and battery supplement mode operation profile.

When V_{IN} is not available, the IC operates in discharge mode, and the battery MOSFET is always fully on to reduce loss.

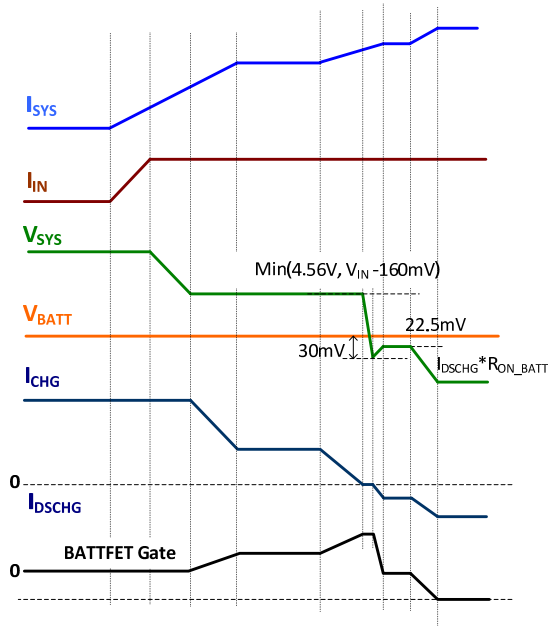


Figure 5: Dynamic Power Management and Battery Supplement Operation Profile

Battery Regulation Voltage

The battery voltage for the constant-voltage regulation phase is V_{BATT_REG}. When V_{BATT_REG} is 4.2V, it has a ±0.5% accuracy over the ambient temperature range of 0°C to +50°C. When the battery is removed, the BATT voltage is between V_{BATT_REG} - V_{RECH} and V_{BATT_REG}.

Thermal Regulation and Thermal Shutdown

The IC monitors the internal junction temperature continuously to maximize power delivery and prevent the chip from overheating. When the internal junction temperature reaches the pre-set limit of T_{J_REG} (default 120°C), the IC reduces the charge current to prevent higher power dissipation. The multiple thermal regulation thresholds from 60°C to 120°C help the system design meet the thermal requirement in different applications. The junction temperature regulation threshold can be set via Reg06 bit[1:0].

When the junction temperature reaches 150°C, both Q1 and Q2 are turned off.

Negative Temperature Coefficient (NTC) Temperature Sensor

NTC allows the IC to sense the battery temperature using the thermistor usually available in the battery pack to ensure a safe operating environment for the chip. A resistor with an appropriate value should be connected from VDD to NTC, and the thermistor should be connected from NTC to ground. The voltage on NTC is determined by the resistor divider, whose divide ratio depends on the temperature. The IC sets a pre-determined upper and lower bound of the divide ratio internally for NTC cold and NTC hot. In the MP2664, the I²C default setting is the PCB OTP. The function can be changed through the I²C (see Table 3).

Table 3: NTC Function Selection Table

I²C Control		Function
EN_NTC	EN_PCB OTP	
0	x	Disable
1	1	NTC
1	0	PCB OTP

When PCB OTP is selected, if the NTC voltage is lower than the NTC hot threshold, both the LDO MOSFET and battery MOSFET are off. The PCB OTP fault sets the NTC_FAULT status (Reg08 bit[1]) to 1 to indicate the fault. Operation resumes once the NTC voltage is higher than the NTC hot threshold.

The NTC function only works in charge mode. Once the NTC voltage goes out of the divide ratio (the temperature is outside the safe operating range), the IC stops the charging and reports it on the status bits. Charging resumes automatically after the temperature falls back to the safe range.

Safety Timer

The IC provides both a pre-charge and a fast-charge safety timer to prevent extended charging cycles due to abnormal battery conditions. The safety timer is one hour when the battery voltage is below V_{BATT_PRE}. The fast-charge safety timer begins when the battery enters constant current fast charging. The fast-charge safety timer can be programmed through the I²C. The safety timer feature can be disabled via the I²C.

The following actions can restart the safety timer:

- A new charge cycle is kicked in
- Reg01 bit[3] is written from 0 to 1 (charge enable)
- Reg05 bit[3] is written from 0 to 1 (safety timer enable)
- Reg01 bit[7] is written from 0 to 1 (software reset)

Host Mode and Default Mode

The IC is a host-controlled device. After the power-on reset, the IC starts in the watchdog timer expiration state or default mode. All of the registers are in the default settings.

Any write to the IC changes it to host mode. All charge parameters are programmable. If the watchdog timer (Reg05 bit[5:4]) is not disabled, the host must reset the watchdog timer regularly by writing 1 to the Reg01 bit[6] before the watchdog timer expires to keep the device in host mode. Once the watchdog timer expires, the IC returns to default mode. The watchdog timer limit can also be programmed or disabled by the host control. When there is no V_{IN}, the watchdog timer is suspended (see Figure 10).

The operation can also be changed to default mode when one of the following conditions occur:

- Refresh input without battery
- Re-insert battery with no V_{IN}
- Register reset Reg01 bit[7] is reset

Battery Discharge Function

If battery is connected and the input source is missing, the battery MOSFET is fully on when V_{BATT} is above the V_{BATT_UVLO} threshold. The 100mΩ battery MOSFET minimizes conduction loss during discharge. The quiescent current of the IC is as low as 11μA in this mode. The low on resistance and low quiescent current help extend the running time of the battery.

Over-Discharge Current Protection

The IC has an over-discharge current protection in discharge mode and supplement mode. Once I_{BATT} exceeds the programmable discharge current limit (default 1.785A), the battery MOSFET is turned off after a 60μs delay, and the MP2664 enters hiccup mode in over-current protection (OCP). The discharge current can be programmed high to 3.2A through the I²C. If the discharge current goes high to reach the internal fixed current limit (about 3.7A), the battery MOSFET is turned off and starts hiccup mode immediately.

Similarly, when the battery voltage falls below the programmable V_{BATT_UVLO} threshold (default 2.8V), the battery MOSFET is turned off to prevent over-discharge.

System Short-Circuit Protection (SCP)

The MP2664 features SYS node short-circuit protection (SCP) for the IN to SYS path and the BATT to SYS path.

The system voltage is monitored continuously. If V_{SYS} is lower than 1.5V, the system (SCP) for the IN to SYS path and the BATT to SYS path are active. I_{DSCHG} is decreased to half of the original value.

1) IN to SYS path: Once I_{IN} is over the protection threshold, both the LDO MOSFET and the BATT MOSFET are turned off immediately, and the IC enters hiccup mode. Otherwise, the max current limit and the setting input current limit are not reached, and I_{IN} is regulated at I_{IN_LIM}. Hiccup mode also starts after a 60μs delay. The interval of the hiccup mode is 800μs.
2) BATT to SYS path: Once I_{BATT} is over the 3.7A protection threshold, both the LDO MOSFET and the BATT MOSFET are turned off immediately, and the IC enters hiccup mode. When the battery discharge current limit threshold is reached, hiccup mode starts after a 60μs delay. The interval of the hiccup mode is 800μs.

If a system short-circuit occurs when both the input and battery are present, the protection mechanism of both paths work, with the faster one dominating the hiccup operation (see Figure 13).

Interrupt to Host (INT)

The IC has an alert mechanism that can output an interrupt signal via INT to notify the system of the operation by outputting a 256μs low-state INT pulse. Any of the below events can trigger the INT output:

- Good input source detected
- UVLO or input over-voltage protection (OVP) charge completed
- Charging status change
- Any fault in Reg08 (watchdog timer fault, input fault, thermal fault, safety timer fault, battery OVP fault, NTC fault)

When any fault occurs, the IC sends out an INT pulse and latches the fault state in Reg08. After the IC exits the fault state, the fault bit can be released to 0 after the host reads Reg08. The NTC fault is not latched and always reports the current thermistor conditions.

Note that the INT needs the external pull-up resistor for its open-drain connection. The resistance should not be lower than 200kΩ.

Battery Disconnect Function

In applications where the battery is not removable, it is essential to disconnect the battery from the system for two reasons: to prevent excessive capacity discharge when the device is in shipping or storage mode, and to allow the system power to reset.

The MP2664 provides both shipping mode and system reset mode for different application requirements.

The register bit FET_DIS (Reg06 bit[5]), allows the IC to enter shipping mode. During normal operation, the battery MOSFET is turned on, and this bit is 0. If this bit is set to 1 through the I²C, the battery MOSFET is turned off, and the MP2664 enters shipping mode. The FET_DIS bit is reset to 0 automatically after the battery MOSFET is turned off (see Figure 6).

The IC can exit shipping mode by pulling INT down. When the IC is in shipping mode and only the battery is present, pull INT down by pushing the push button (PB) to wake the MP2664 up from shipping mode (see Table 4).

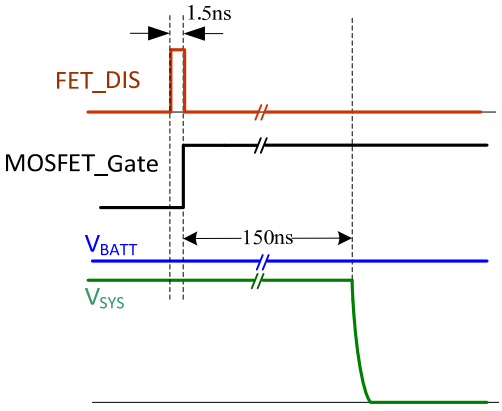


Figure 6: Time Delay from when FET_DIS is written to 1 to the Battery MOSFET Turning Off

Table 4: Exit the Shipping Mode with BATT Present Only

	INT Signal	IC Exits Shipping Mode
Case 1	INT = low twice with the rising edge >600ns	At once
Case 2	INT = low once with the rising edge >600ns	After 4s
Case 3	INT = low for 4s	After 4s
Case 4	INT = low with the rising edge in ms level	At once

The MP2664 can also wake up from shipping mode when a valid V_{IN} powers on (see Table 5). After V_{IN} is preset, the MP2664 pulls INT low to indicate the event "Good input source detected" if V_{IN} is in the operating range. Then, the MP2664 can be woken up from shipping mode by the INT signal (see Figure 7).

Table 5: Exiting Shipping Mode when V_{IN} Powers On

	INT Signal	IC Exits Shipping Mode
Case 1	INT= low twice with the rising edge >600ns	At once
Case 2	INT= low once with the rising edge >600ns	After 4s
Case 3	INT = low with the rising edge in ms level	At once

If FET_DIS is set to 1 during shipping mode, the IC can wake up after keeping INT low for 4s. In this case, the FET_DIS bit cannot be reset to 0 automatically—it must be reset to 0 manually through the I²C.

The IC can use INT to cut off the path from the battery to the system when a system reset is needed.

Once the logic at INT is set to low for more than 16s, the battery is disconnected from the system by turning off the battery MOSFET.

The off state lasts for 4s, and then the battery MOSFET is turned on automatically. The system is powered by the battery again. During the 4s off period, the INT pin voltage level can be high or low. The IC can reset the system by controlling INT (see Figure 8).

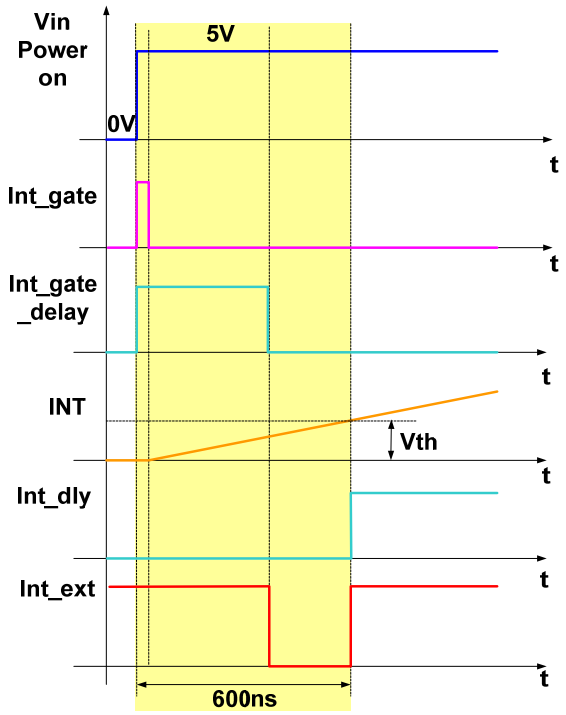


Figure 7: INT Signal during V_{IN} Power On

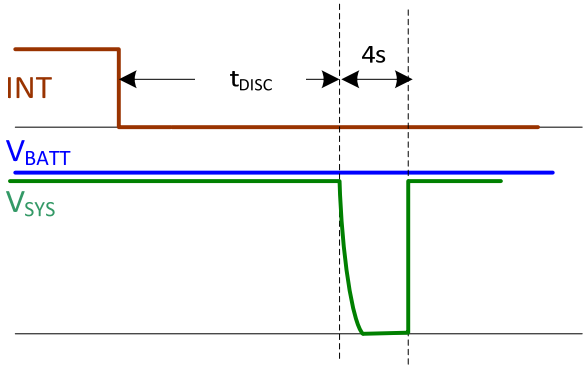


Figure 8: System Reset Function Operation Profile

I²C REGISTER MAP

IC Address: 09H (reserved some trim options)

Input Source Control Register/Address: 00H (Default: 0100 1111)

Bit	Symbol	Description	Read/Write	Default
Bit 7	EN_HIZ (7)	0: disable 1: enable	r/w	Disable (0)
Input Minimum Voltage Regulation				
Bit 6	V_{IN_MIN} [3]	640mV	r/w	Offset: 3.88V Range: 3.88V - 5.08V Default: 4.60V (1001)
Bit 5	V_{IN_MIN} [2]	320mV		
Bit 4	V_{IN_MIN} [1]	160mV		
Bit 3	V_{IN_MIN} [0]	80mV		
Input Current Limit				
Bit 2	I_{IN_LIM} [2]	000: 85mA 001: 130mA 010: 175mA 011: 220mA 100: 265mA 101: 310mA 110: 355mA 111: 455mA	r/w	455mA (111)
Bit 1	I_{IN_LIM} [1]			
Bit 0	I_{IN_LIM} [0]			

NOTE:

7) This bit only controls the on and off of the LDO MOSFET.

Power-On Configuration Register/Address: 01H (Default: 0000 0100)

Bit	Symbol	Description	Read/Write	Default
Bit 7	Register reset	0: keep current setting 1: reset	r/w	Keep current setting (0)
Bit 6	I²C watchdog timer reset	0: normal 1: reset	r/w	Normal (0)
Bit 5	Reserved		r/w	Reserved
Bit 4	Reserved		r/w	Reserved
Charger Configuration				
Bit 3	CEB	0: charge enabled 1: charge disabled	r/w	Charge enabled (0)
Battery UVLO Threshold				
Bit 2	V_{BATT_UVLO} [2]	0.4V	r/w	Offset: 2.4V Range: 2.4V - 3.1V Default: 2.8V (100)
Bit 1	V_{BATT_UVLO} [1]	0.2V		
Bit 0	V_{BATT_UVLO} [0]	0.1V		

Charge Current Control Register/Address: 02H (Default: 0000 1110)

Bit	Symbol	Description	Read/Write	Default
Bit 7	Reserved		r/w	Reserved
Bit 6	Reserved		r/w	Reserved
Bit 5	Reserved		r/w	Reserved
Fast-Charge Current Setting				
Bit 4	I_{CC} [4]	272mA	r/w	Offset: 8mA Range: 8mA - 535mA Default: 246mA (01110)
Bit 3	I_{CC} [3]	136mA		
Bit 2	I_{CC} [2]	68mA		
Bit 1	I_{CC} [1]	34mA		
Bit 0	I_{CC} [0]	17mA		

Pre-Charge/Termination Current/Address: 03H (Default: 0100 1010)

Bit	Symbol	Description	Read/Write	Default
Bit 7	Reserved		r/w	Reserved
BATT to SYS Discharge Current Limit				
Bit 6	I_{DSCHG} [3]	1600mA	r/w	Offset: 200mA Range: 400mA - 3.2A Valid range: 0001 - 1111 Default: 2000mA (1001)
Bit 5	I_{DSCHG} [2]	800mA		
Bit 4	I_{DSCHG} [1]	400mA		
Bit 3	I_{DSCHG} [0]	200mA		
PCB OTP Enable				
Bit 2	EN_PCB OTP	0: enable 1: disable	r/w	Enable(0)
Pre-Charge Current				
Bit 1	I_{PRE} [1]	14mA	r/w	Offset: 6mA Range: 6mA - 27mA Default: 20mA (10) I_{PRE}[1:0] also sets termination current
Bit 0	I_{PRE} [0]	7mA		

Charge Voltage Control Register/Address: 04H (Default: 1010 0011)

Bit	Symbol	Description	Read/Write	Default
Battery Regulation Voltage				
Bit 7	V_{BATT_REG} [5]	480mV	r/w	Offset: 3.60V Range: 3.60V - 4.545V Default: 4.2V (101000)
Bit 6	V_{BATT_REG} [4]	240mV		
Bit 5	V_{BATT_REG} [3]	120mV		
Bit 4	V_{BATT_REG} [2]	60mV		
Bit 3	V_{BATT_REG} [1]	30mV		
Bit 2	V_{BATT_REG} [0]	15mV		
Pre-Charge to Fast Charge Threshold				
Bit 1	V_{BATT_PRE}	0: 2.8V 1: 3.0V	r/w	3.0V (1)
Battery Recharge Threshold (below V_{BATT_REG})				
Bit 0	V_{RECH}	0: 150mV 1: 300mV	r/w	300mV (1)

Charge Termination/Timer Control Register/Address: 05H (Default: 0100 1010)

Bit	Symbol	Description	Read/Write	Default
Bit 7	Reserved		r/w	Reserved
Termination Setting (the termination is allowed or not)				
Bit 6	EN_TERM	0: disable 1: enable	r/w	Enabled (1)
I²C Watchdog Timer Limit				
Bit 5	WATCHDOG [1]	00: disable timer 01: 40s 10: 80s 11: 160s	r/w	Disable timer (00)
Bit 4	WATCHDOG [0]			
Safety Timer Setting				
Bit 3	EN_TIMER	0: disable 1: enable	r/w	Enable timer (1)
Fast-Charge Timer				
Bit 2	CHG_TMR [1]	00: 3hrs 01: 5hrs 10: 8hrs 11: 12hrs	r/w	5hrs (01)
Bit 1	CHG_TMR [0]			
Termination Timer Control (when TERM_TMR is enabled, the IC will not suspend the charge current after charge termination)				
Bit 0	TERM_TMR	0: disable 1: enable	r/w	(0)

Miscellaneous Operation Control Register/Address: 06H (Default: 0100 1011)

Bit	Symbol	Description	Read/Write	Default
Bit 7	Reserved		r/w	Read/write
Bit 6	Reserved		r/w	This bit must be set to 0
Bit 5	FET_DIS (8)	0: enable 1: turn off	r/w	Enabled (0)
Bit 4	Reserved		r/w	(0)
Bit 3	EN_NTC	0: disable 1: enable	r/w	Enabled (1)
Bit 2	Reserved		r/w	
Thermal Regulation Threshold				
Bit 1	T_{J_REG} [1]	00: 60°C 01: 80°C 10: 100°C 11: 120°C	r/w	120°C (11)
Bit 0	T_{J_REG} [0]			

NOTE:
8) This bit controls the on and off of the battery MOSFET, including the charging and discharging.

System Status Register/Address: 07H (Default: 0000 0000)

Bit	Symbol	Description	Read/Write	Default
Bit 7	Reserved		r	Reserved
Revision				
Bit 6	Rev [1]	Revision number	r	(00)
Bit 5	Rev [0]			
Bit 4	CHG_STAT [1]	00: not charging 01: pre-charge 10: charge 11: charge done	r	Not charging (00)
Bit 3	CHG_STAT [0]			
Bit 2	PPM_STAT	0: no PPM 1: in PPM	r	No PPM (0) (no power-path management happens)
Bit 1	PG_STAT	0: power fail 1: power good	r	Not power good (0)
Bit 0	THERM_STAT	0: no thermal regulation 1: in thermal regulation	r	Normal (0)

Fault Register/Address: 08H (Default: 0000 0000)

Bit	Symbol	Description	Read/Write	Default
Bit 7	Reserved		r	Reserved
Bit 6	WATCHDOG_FAULT	0: normal 1: watchdog timer expiration	r	Normal (0)
Bit 5	VIN_FAULT	0: normal 1: input fault (OVP or bad source)	r	Normal (00)
Bit 4	THEM_SD	0: normal 1: thermal shutdown	r	
Bit 3	BAT_FAULT	0: normal 1: battery OVP	r	Normal (0)
Bit 2	STMR_FAULT	0: normal 1: safety timer expiration	r	Normal (0)
Bit 1	NTC_FAULT [1]	0: normal 1: NTC hot	r	Normal (00)
Bit 0	NTC_FAULT [0]	0: normal 1: NTC cold		

OTP MAP

#	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
0x02	N/A			I_{CC}: **8mA - 535mA / 17mA** step				
0x03	N/A					EN_PCB_OTP	I_{PRE}	
0x04	V_{BATT_REG}: **3.6V - 4.545V / 15mV** step						N/A	
0x05	N/A		WATCHDOG		N/A			

OTP DEFAULT

OTP Items	Default
I_{CC}	246mA
I_{PRE}	20mA
V_{BATT_REG}	4.2V
WATCHDOG	Disable timer
EN_PCB OTP	Enable

STATE CONVERSION CHART

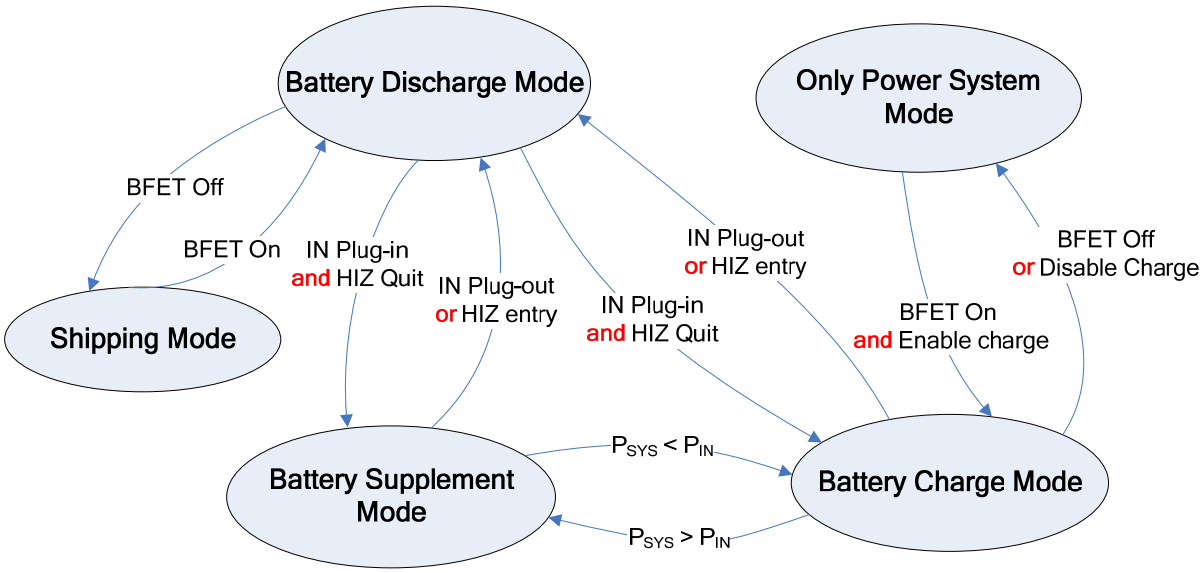


Figure 9: State Machine Conversion

CONTROL FLOW CHART

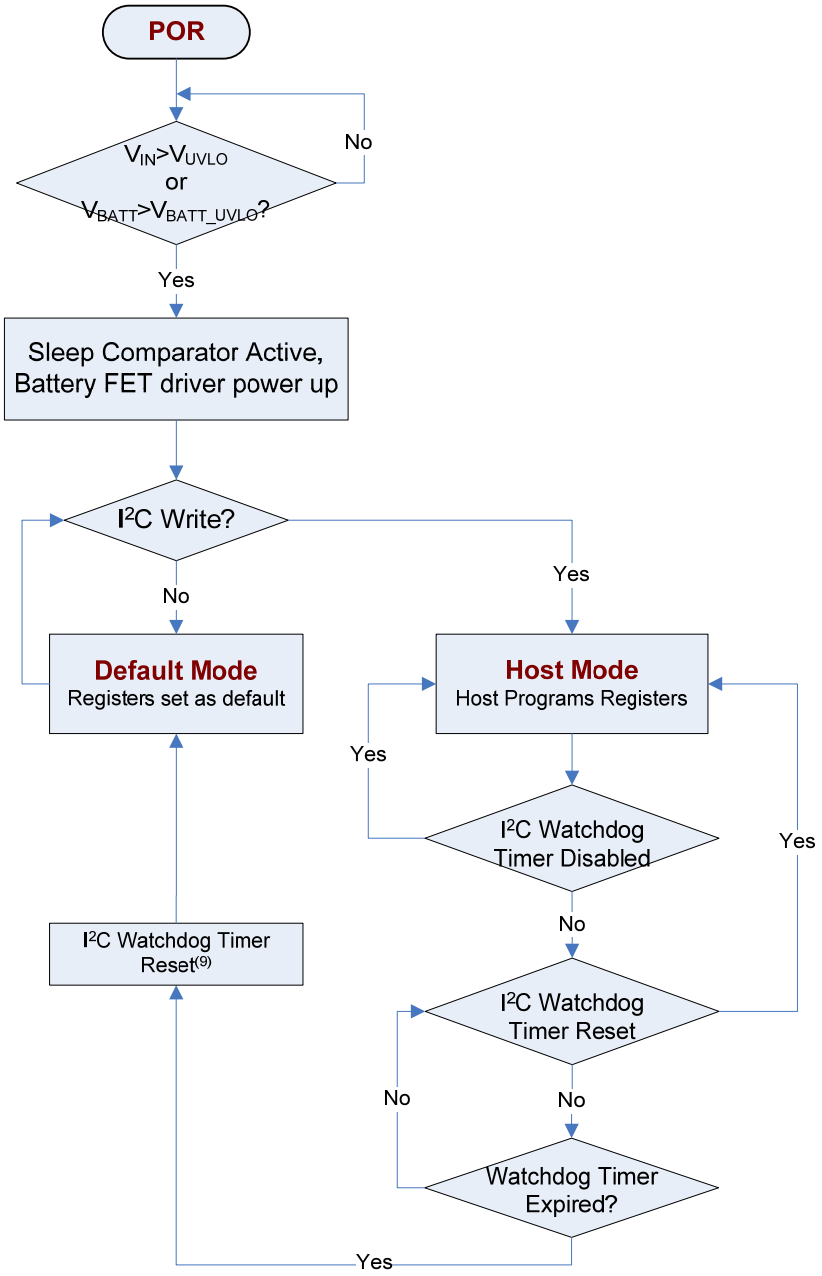


Figure 10: Default Mode and Host Mode Selection (10)

NOTES:
9) Once the watchdog timer expires, the I²C watchdog timer must be reset, or the watchdog timer is not valid in the next cycle.
10) The watchdog timer is held when V_{IN} is not present.

CONTROL FLOW CHART *(continued)*

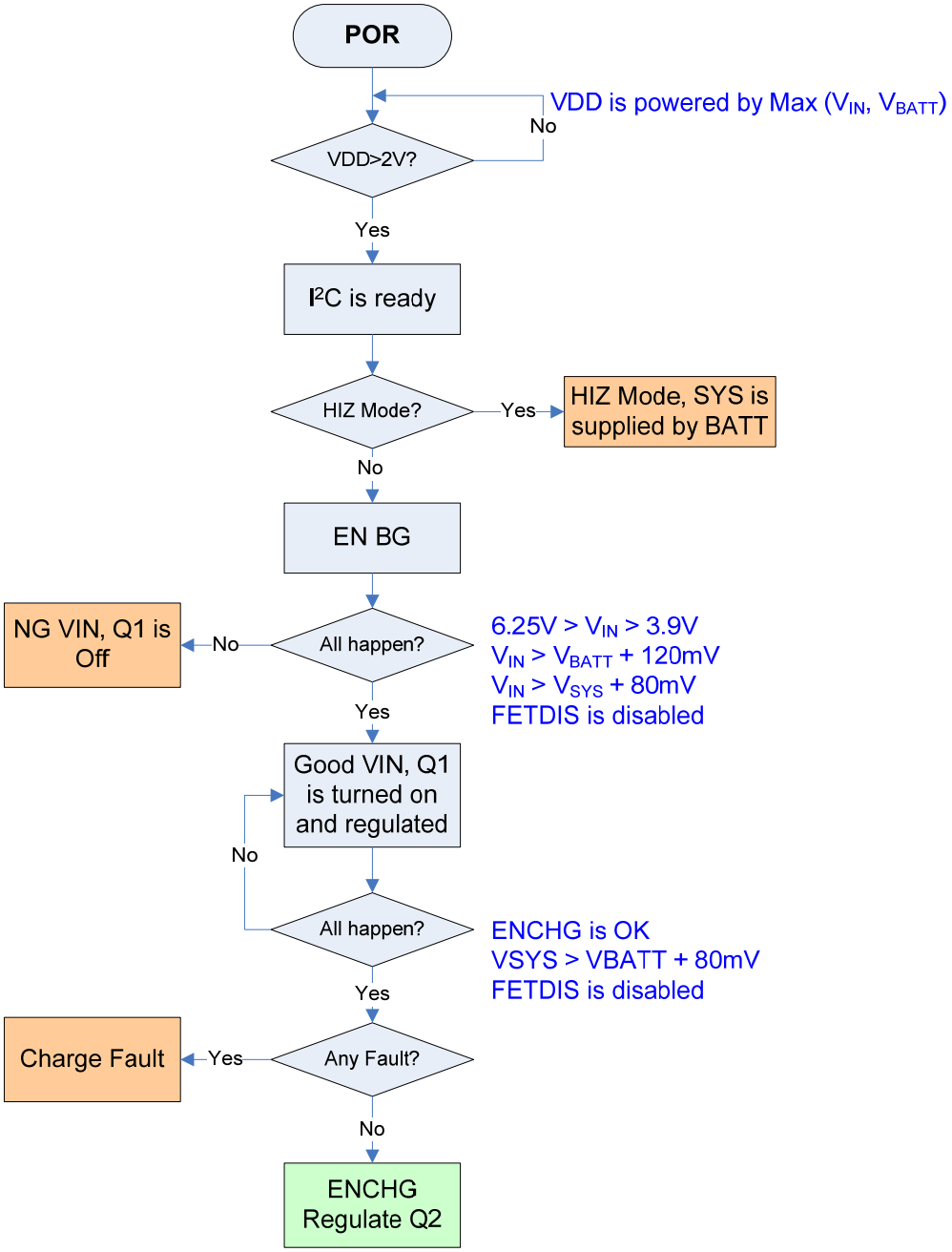


Figure 11: Input Power Start-Up Flow Chart

CONTROL FLOW CHART *(continued)*

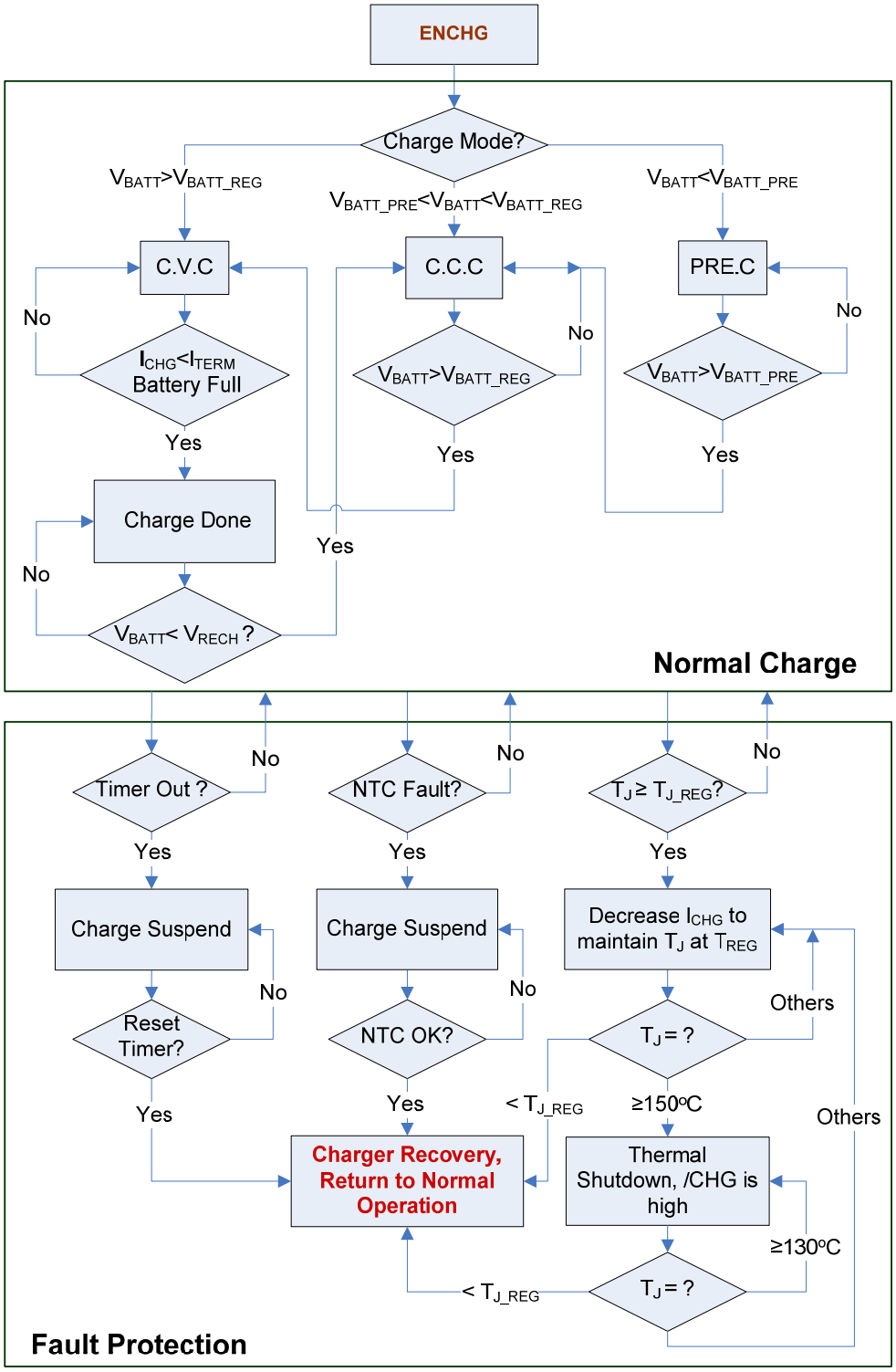


Figure 12: Charging Process

CONTROL FLOW CHART *(continued)*

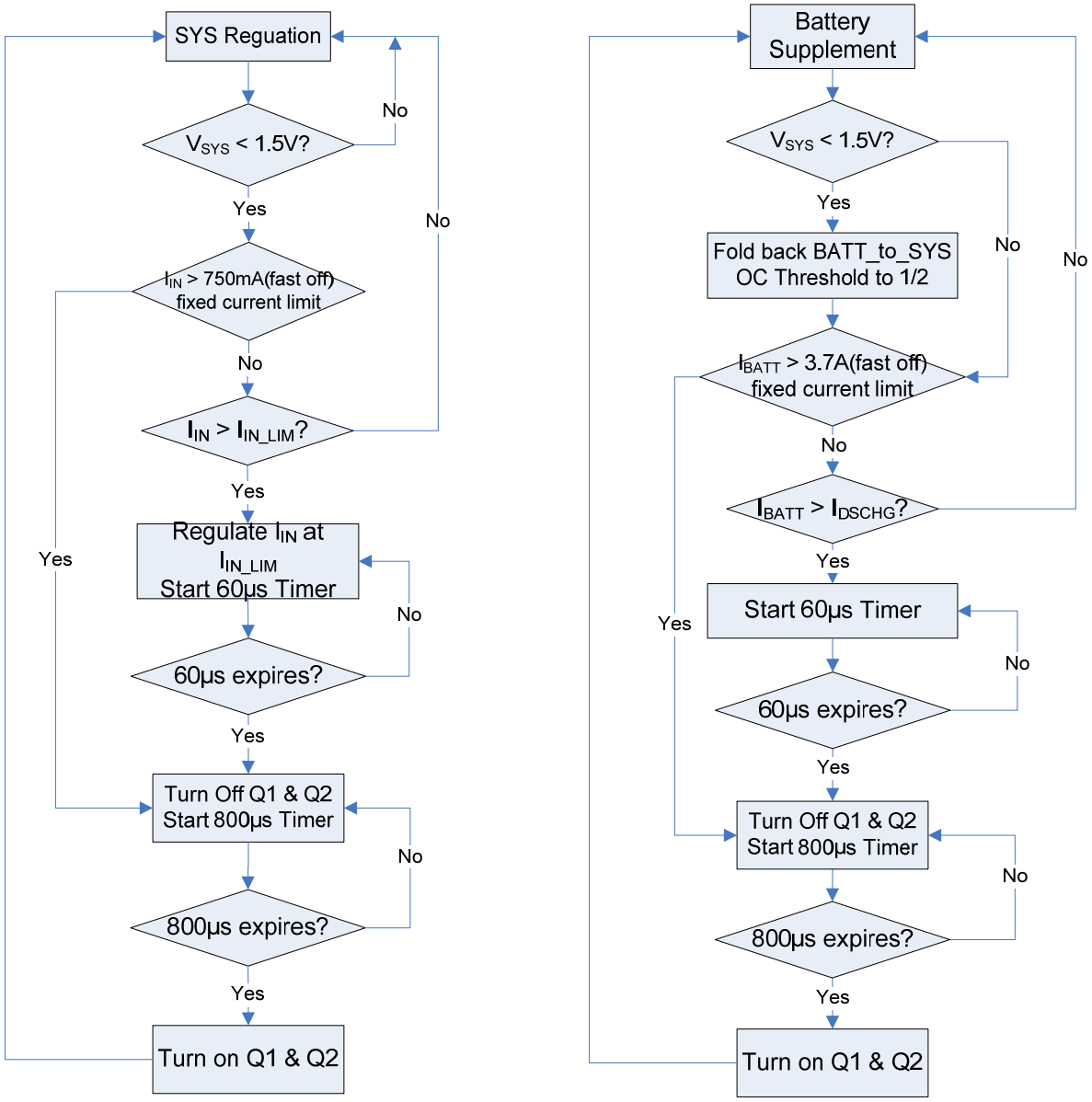


Figure 13: System Short-Circuit Protection

APPLICATION INFORMATION

Selecting a Resistor for the NTC Sensor

NTC uses a resistor divider from the input source (VDD) to sense the battery temperature. The two resistors (R_{T1} and R_{T2}) allow the high temperature limit and low temperature limit to be programmed independently (see Figure 14). In other words, the IC can fit most types of NTC resistors and different temperature operation range requirements with the two extra resistors.

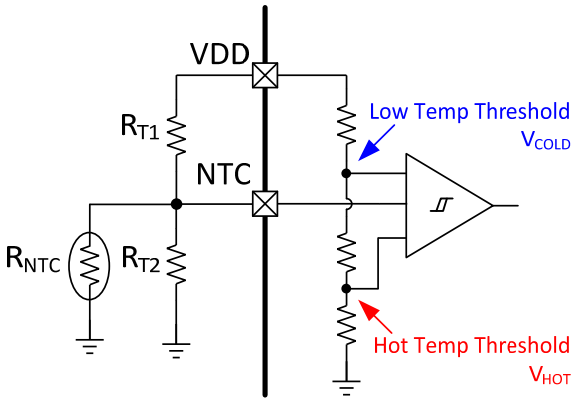


Figure 14: NTC Function Block

For a given NTC thermistor, R_{T1} and R_{T2} depend on the type of NTC resistor used and can be calculated with Equation (1) and Equation (2):

$$R_{T2} = \frac{(V_{COLD} - V_{HOT}) \times R_{NTCH} \times R_{NTCL}}{(V_{HOT} - V_{COLD} V_{HOT}) \times R_{NTCL} - (V_{COLD} - V_{COLD} V_{HOT}) \times R_{NTCH}} \quad (1)$$

$$R_{T1} = \frac{1\text{-}V_{COLD}}{V_{COLD}} \times (R_{T2} // R_{NTCL}) \quad (2)$$

Where R_{NTCH} is the value of the NTC resistor at the high temperature of the required temperature operating range, and R_{NTCL} is the value of the NTC resistor at a low temperature.

For example, for thermistor NCP18XH103, R_{NTCL} is 27.219kΩ at 0°C, and R_{NTCH} is 4.161kΩ at 50°C. Equation (1) and Equation (2) determine that R_{T1} = 7.01kΩ and R_{T2} = 27.21kΩ (assuming that the NTC window is between 0°C and 50°C and using the V_{COLD} and V_{HOT} values from the EC table on page 8).

Selecting the External Capacitor

Like most low-dropout regulators, the MP2664 requires external capacitors for regulator stability and voltage spike immunity. The MP2664 is designed specifically for portable applications requiring a minimal board space and small components. These capacitors must be selected correctly for optimal performance.

An input capacitor is required for stability. Connect a 1µF (minimum) capacitor between IN and GND for stable operation over the entire load current range. There can be more output capacitance than input as long as the input is at least 1µF.

The IC is designed specifically to work with a very small ceramic output capacitor. A >2.2µF ceramic capacitor with X5R or X7R type dielectrics is suitable in the MP2664 application circuit. For the MP2664, the output capacitor should be connected between SYS and GND with thick traces and a small loop area.

A capacitor from BATT to GND is necessary for the MP2664. A >2.2µF ceramic capacitor with X5R or X7R type dielectrics is suitable for the application circuit.

A capacitor between VDD and GND is used to stabilize the VDD voltage to power the internal control and logic circuit. The typical value of this capacitor is 100nF.

PCB Layout Guidelines

Efficient PCB layout is critical for stable operation. For best results, follow the guidelines below.

1. Place the external capacitors as close to the IC as possible to ensure the smallest input inductance and ground impedance.
2. Place the PCB trace connecting the capacitor between VDD and GND very close to the IC.
3. Keep the GND for the I²C wire clean and away from GND.
4. Place the I²C wire in parallel.

TYPICAL APPLICATION CIRCUIT

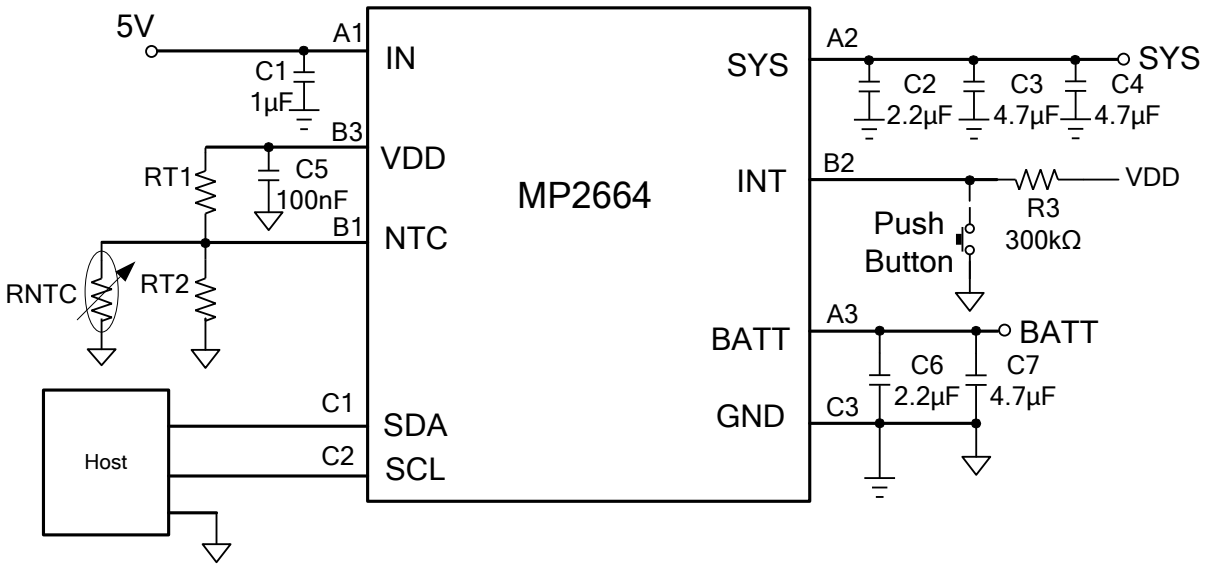


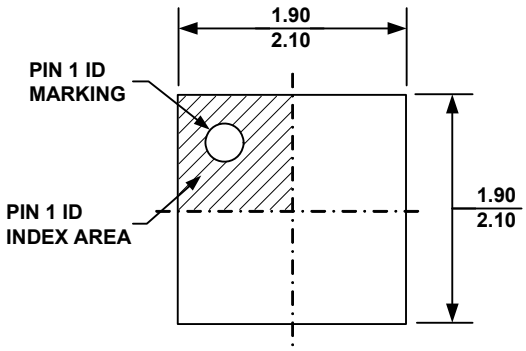
Figure 15: MP2664 Typical Application Circuit with 5V Input

Table 6: Key BOM from Figure 15

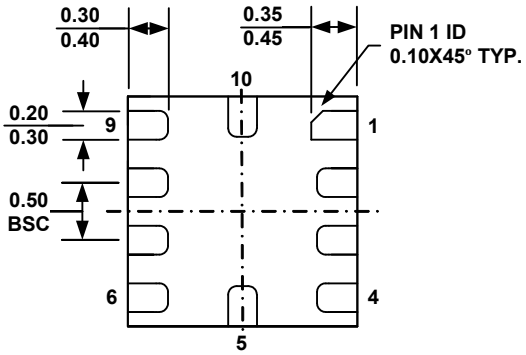
Qty	Ref	Value	Description	Package	Manufacture
1	C1	1µF	Ceramic Capacitor;16V; X5R or X7R	0603	Any
2	C2, C6	2.2µF	Ceramic Capacitor;16V; X5R or X7R	0603	Any
1	C3, C4, C7	4.7µF	Ceramic Capacitor; 16V; X5R or X7R	0603	Any
1	C5	100nF	Ceramic Capacitor;16V; X5R or X7R	0603	Any

PACKAGE INFORMATION

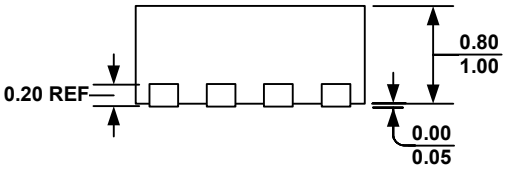
QFN-10 (2mmx2mm)



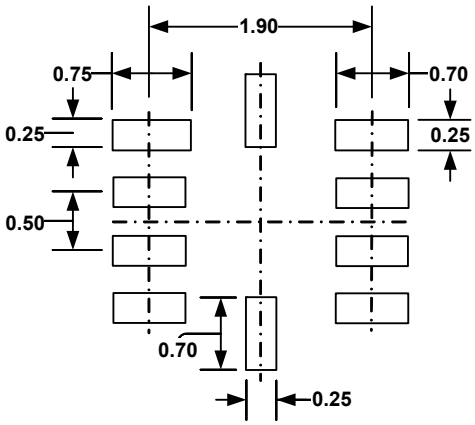
TOP VIEW



BOTTOM VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN

NOTE:

1) ALL DIMENSIONS ARE IN MILLIMETERS.
2) EXPOSED PADDLE SIZE DOES NOT INCLUDE MOLD FLASH.
3) LEAD COPLANARITY SHALL BE 0.10 MILLIMETER MAX.
4) JEDEC REFERENCE IS MO-220, VARIATION VCCD.
5) DRAWING IS NOT TO SCALE.